Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
ICK PGA 6 x 6 x 14	B 10	18.60	6.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 8 x 8 x 12	B 10	14.80	8.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 9 x 9	B 10	14.00	3.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 11 x 11 x 8	B 10	16.00	7.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 11 x 11	B 10	10.90	4.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 11 x 11 x 12	B 11	12.30	3.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 14 x 14	B 11	10.00	4.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 14 x 14 x 10	B 11	10.50	11.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 14 x 14 x 14	B 11	9.60	12.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 14 x 14 x 12	B 11	9.80	5.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 15 x 15	B 11	9.40	5.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 16 x 16 x 8	B 12	14.00	4.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 16 x 16 x 10	B 12	10.50	12.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 16 x 16 x 12	B 12	9.30	6.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 17 x 17	B 12	8.60	6.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 17 x 17 x 8	B 12	13.20	5.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 17 x 17 x 12	B 12	9.00	6.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 18 x 18	B 13	8.40	7.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 19 x 19	B 13	8.10	7.60	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 19 x 19 x 12	B 13	8.80	6.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 20 x 20	B 13	7.60	8.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 20 x 20 K	B 13	7.60	8.30	fixing clamp	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A
ICK PGA 20 x 20 x 8	B 14	12.00	6.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 20 x 20 x 8 K	B 14	12.00	6.30	fixing clamp	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A
ICK PGA 20 x 20 x 10	B 14	8.50	15.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 20 x 20 x 12	B 14	8.00	8.10	therm. conductive foil/ therm. cond. adhesive	universal	universal

Heatsinks for power-pc → **B 41**
Heatsinks for PLCC → **B 37**
Heatsinks for DIL-IC → **B 36**
Heatsinks for microprocessors → **B 41**
Pin heatsinks for IC → **B 20 – 24**
Heatsinks for BGA → **B 16 – 19**
Heatsinks for PGA → **B 10 – 15**
SMD-heatsinks → **B 38 – 40**

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Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
ICK PGA 20 x 20 x 12 K	B 14	8.00	8.10	fixing clamp	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A
ICK PGA 21 x 21	B 15	7.00	8.60	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 22 x 22	B 15	6.20	8.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PGA 25 x 25	B 15	5.00	11.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 10 x 10	B 16	31.00	1.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 10 x 10 x 10	B 16	28.50	1.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 14 x 14	B 16	29.00	2.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 14 x 14 x 10	B 16	27.40	2.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 21 x 21	B 16	24.30	2.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 23 x 23	B 17	22.00	2.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 23 x 23 x 10	B 17	21.00	2.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 27 x 27	B 17	20.00	3.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 27 x 27 x 10	B 17	18.50	3.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 27 x 27 x 14	B 17	13.50	9.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 27 x 27 x 22	B 17	13.50	9.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 31 x 31	B 18	18.60	3.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 31 x 31 x 10	B 18	17.00	3.70	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 35 x 35	B 18	16.50	3.70	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 35 x 35 x 10	B 18	15.70	3.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 37 x 37 x 6	B 18	15.70	9.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 37 x 37 x 10	B 18	14.00	10.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 40 x 40	B 19	14.30	4.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 40 x 40 x 10	B 19	13.80	4.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK BGA 42,5 x 45	B 19	13.60	4.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 10 x 10 x 6,5	B 20	29.90	2.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 10 x 10 x 12,5	B 20	26.30	2.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 14 x 14 x 6,5	B 20	10.00	5.00	therm. conductive foil/ therm. cond. adhesive	universal	universal

Heatsinks for power-pc → **B 41**
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Heatsinks for DIL-IC → **B 36**
Heatsinks for microprocessors → **B 41**
Pin heatsinks for IC → **B 20 – 24**
Heatsinks for BGA → **B 16 – 19**
Heatsinks for PGA → **B 10 – 15**
SMD-heatsinks → **B 38 – 40**

Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
ICK S 14 x 14 x 10	B 21	9.80	5.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 17 x 17 x 15	B 21	8.36	5.95	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 17 x 17 x 20	B 21	7.89	6.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 18 x 18 x 6,5	B 21	7.00	7.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 18 x 18 x 10	B 21	6.80	7.35	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 25 x 25 x 6,5	B 21	5.80	12.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 25 x 25 x 12,5	B 21	5.30	14.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 25 x 25 x 18,5	B 22	5.20	14.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 29 x 29 x 10	B 22	5.70	13.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 29 x 29 x 20	B 22	3.70	20.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 32 x 32 x 10	B 22	5.40	13.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 32 x 32 x 20	B 22	3.70	20.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 36 x 36 x 10	B 22	4.70	16.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 36 x 36 x 15	B 23	3.90	19.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 36 x 36 x 20	B 23	3.20	23.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 40 x 40 x 10	B 23	4.60	16.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 40 x 40 x 20	B 23	3.50	21.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 45 x 45 x 10	B 23	4.70	16.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 45 x 45 x 20	B 23	4.40	17.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 20	B 24	2.70	27.70	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 25	B 24	2.40	31.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 40	B 24	6.05	13.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 50 x 50 x 50	B 24	4.05	14.32	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S 98 x 98 x 45	B 24	3.50	42.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S D 12 x 12 x 7,5	B 25	10.85	4.60	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S D 18 x 12 x 7,5	B 25	9.00	5.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S D 24 x 18 x 7,5	B 25	8.50	5.85	therm. conductive foil/ therm. cond. adhesive	universal	universal

Heatsinks for power-pc → **B 41**
Heatsinks for PLCC → **B 37**
Heatsinks for DIL-IC → **B 36**
Heatsinks for microprocessors → **B 41**
Pin heatsinks for IC → **B 20 – 24**
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SMD-heatsinks → **B 38 – 40**

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Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
ICK S D 98 x 98 x 10	B 25	4.88	10.25	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 28,5 x 6,5	B 26	5.82	15.60	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 28,5 x 10	B 26	5.65	16.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 28,5 x 12,5	B 26	5.53	16.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 28,5 x 18,5	B 26	4.25	20.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 32,5 x 10	B 26	5.54	9.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 32,5 x 20	B 26	5.60	8.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 36,5 x 20	B 26	6.41	18.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 40 x 10	B 27	11.04	8.40	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 40 x 20	B 27	10.32	8.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R A 40 x 20	B 27	11.62	8.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 40 x 30	B 27	9.77	9.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 50 x 10	B 27	5.28	9.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 50 x 20	B 27	8.55	9.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 50 x 30	B 28	8.26	10.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 50 x 45	B 28	6.32	12.70	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 54 x 20	B 28	8.11	10.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 54 x 30	B 28	6.95	11.57	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK S R 54 x 45	B 28	5.37	15.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 23,5 x 14	B 29	18.58	6.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 23,5 x 14 G	B 29	19.16	6.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 27 x 10	B 29	17.69	6.70	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 27 x 10 G	B 29	18.24	6.60	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 28 x 15	B 29	15.24	7.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 28 x 15 G	B 30	15.72	7.60	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 29 x 11,5	B 30	17.26	8.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 29 x 11,5 G	B 30	17.80	8.00	therm. conductive foil/ therm. cond. adhesive	universal	universal

Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
ICK LED R 32 x 14	B 30	15.71	7.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 32 x 14 G	B 30	15.23	7.60	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 33 x 10	B 30	17.60	6.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 33 x 10 G	B 30	18.15	6.60	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 33 x 16,5	B 31	13.87	8.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 33 x 16,5 G	B 31	14.30	8.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 35 x 10	B 31	16.90	9.35	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 35 x 10 G	B 31	17.50	9.20	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 36 x 12	B 31	12.88	10.00	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 36 x 12 G	B 31	13.28	8.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 40 x 10	B 31	12.28	9.45	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 40 x 10 G	B 32	12.66	9.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 40 x 27	B 32	9.41	12.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 40 x 27 G	B 32	9.71	11.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 45,7 x 16,5	B 32	10.46	11.05	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 45,7 x 16,5 G	B 32	10.79	10.80	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 50 x 10	B 32	10.57	10.50	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 50 x 10 G	B 32	10.90	10.30	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 50,8 x 16,5	B 33	10.17	11.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 50,8 x 16,5 G	B 33	10.49	10.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 54 x 20	B 33	9.48	12.10	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK LED R 54 x 20 G	B 33	9.78	11.90	therm. conductive foil/ therm. cond. adhesive	universal	universal
ICK PPC 51	B 41	8.10	14.00	screw fastening	–	Power PC
ICK PEN 3 XE	B 41	2.00	31.30	screw fastening	Slot 2	Intel® Pentium® III-Xeon™ Slot II Format
ICK PEN 3 XE 1	B 41	1.80	33.60	screw fastening	Slot 2	Intel® Pentium® III-Xeon™ Slot II Format
SK 428 43 SA	B 41	9.00	6.60	integrated clamp	PGA socket	Intel® 80486
SK 430 50 SA	B 41	7.60	7.80	integrated clamp	PGA socket	Intel® Pentium®
SK 449 50 SA	B 41	7.90	8.10	integrated clamp	PGA socket	Intel® Pentium® 200/ MMX

Heatsinks for power-pc → **B 41**
Heatsinks for PLCC → **B 37**
Heatsinks for DIL-IC → **B 36**
Heatsinks for microprocessors → **B 41**
Pin heatsinks for IC → **B 20 – 24**
Heatsinks for BGA → **B 16 – 19**
Heatsinks for PGA → **B 10 – 15**
SMD-heatsinks → **B 38 – 40**

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Heatsinks for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
ICK PEN 38 F	B 42	4.00	15.10	thermally conductive foil	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A
ICK PEN 38 K	B 42	4.00	15.10	fixing clamp	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A
ICK PEN 38 W	B 42	4.00	15.10	thermally conductive adhesive	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A
ICK PEN 45 W	B 42	3.50	21.00	thermally conductive adhesive	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A
ICK PRO 40 W	B 42	2.70	22.00	thermally conductive adhesive	socket 8	Intel® Pentium® PRO
ICK PEN 3 FC	B 42	3.50	22.00	fixing clamp	socket 7/ socket 370	Intel® Pentium® III FC PGA (Mendocino, Coppermine)

Fan coolers for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
LA ICK 15 x 15 F 05	B 43	2.30	22.2	thermally conductive foil	universal	universal
LA ICK 15 x 15 F 12	B 43	2.30	22.2	thermally conductive foil	universal	universal
LA ICK 17 x 17 F 12	B 43	1.60	35.8	thermally conductive foil	universal	universal
LA ICK 17 x 17 F 12 A	B 43	1.60	35.8	thermally conductive foil	universal	universal
LA ICK 17 x 17 W 05	B 43	1.60	35.8	thermally conductive adhesive	universal	universal
LA ICK 17 x 17 W 12	B 43	1.60	35.8	thermally conductive adhesive	universal	universal
LA ICK 18 x 18 F 12	B 43	1.50	41.7	thermally conductive foil	universal	universal
LA ICK 18 x 18 W 12	B 43	1.50	41.7	thermally conductive adhesive	universal	universal
LA ICK 21 x 21 F 05	B 43	1.40	46.3	thermally conductive foil	universal	universal
LA ICK 21 x 21 F 12	B 43	1.40	46.3	thermally conductive adhesive	universal	universal
LA ICK 21 x 21 W 05	B 43	1.40	46.3	thermally conductive adhesive	universal	universal
LA ICK 21 x 21 W 12	B 43	1.40	46.3	thermally conductive adhesive	universal	universal
LAK ICK 17 X 17	B 43	1.90	29.4	integrated clamp	PGA socket	Intel® 80486
LAK ICK 21 X 21	B 43	1.60	38.6	integrated clamp	PGA socket	Intel® Pentium®
LAK ICK PEN 200	B 43	1.80	38.1	integrated clamp	PGA socket	Intel® Pentium® 200/ MMX
LA ICK PEN 8 F 05	B 44	2.50	23.4	thermally conductive foil	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 8 F 12	B 44	2.50	23.4	thermally conductive foil	socket 370/ socket 7	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 8 W 05	B 44	2.50	23.4	thermally conductive adhesive	socket 370/ socket 7	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 8 W 12	B 44	2.50	23.4	thermally conductive adhesive	socket 370/ socket 7	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 16 K 12	B 44	1.20	51.1	fixing clamp	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 16 W 12	B 44	1.20	51.1	thermally conductive adhesive	socket 370/ socket 7	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 16 W 12 A	B 44	1.20	51.1	thermally conductive adhesive	socket 370/ socket 7	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 18 K 05	B 44	1.60	38.6	fixing clamp	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 18 W 12	B 44	1.60	38.6	thermally conductive adhesive	socket 370/ socket 7	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar

Heatsinks for BGA → **B 16 – 19**
Heatsinks for PGA → **B 10 – 15**
Heatsinks for microprocessors → **B 41**
Heatsinks for Pentium PRO → **B 41**
Heatsinks for P II-Mobile Module → **B 41**
Heatsinks for Pentium III-Xeon → **B 41**
Heatsinks for Pentium III-Xeon → **B 41 – 15**
Thermal conduct. foil WLFT 404/405 → **B 45**

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Fan coolers for IC processor

art. no.	page	R_{th} [K/W]	dissipation loss [W]	mounting method	socket	suitable for processor type
LA ICK PEN 38 K 12	B 44	1.10	53.6	fixing clamp	socket 7/ socket 370	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PEN 38 W 12	B 44	1.10	53.6	thermally conductive adhesive	socket 370/ socket 7	Intel® Pentium®/ MMX/ AMD® K6-2/ AMD® K6-III/ IDT C6/ IDT W2A/ Cyrix M II and similar
LA ICK PRO 25 F 12	B 44	0.97	60.0	thermally conductive foil	socket 8	Intel® Pentium® PRO
LA ICK PEN 2 K	B 45	1.20	58.0	fixing clamp	Slot 1/ Slot A	AMD® Athlon®/ Intel® Pentium® II
LA ICK PEN 3 XE	B 45	0.80	61.8	screw fastening	Slot 2	Intel® Pentium® III-Xeon™
LA ICK PEN 4 1 K	B 45	0.60	85.0	fixing clamp	socket 423/ socket 463	Intel® Pentium® IV

Heatsinks
- excellent thermal efficiency achieved by flow-favorable omnidirectional fin geometry and black anodised surface
- easy mounting using fixing clamp, thermally conductive adhesive foil or thermally conductive glue

Fan coolers
- special high-grade industrial type
- compact design with high mechanical stability
- fan motor axle with double ball bearings ensures high reliability and long product life
- low current consumption and thus low self-heating
- effctive heat dissipation achieved by optimum design of fan motor and heatsink
- fan motors with other operating voltages on request
- fan motors also available with pulse output and alarm device cicuit

Technical introduction
- the thermal resitances and the power dissipation were determined with an ambient temperature of 25 °C and an IC case-temeperature of 85 °C
- with higher IC case-temperature, the power to be dissipated icreases proportionally

Fixing methods

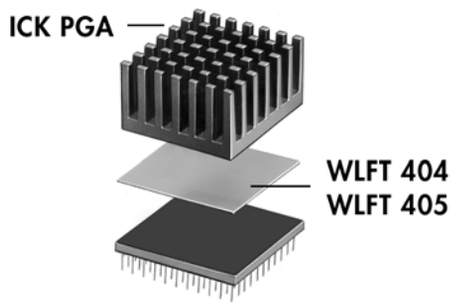
K = fixing clamp, **F** = double sided thermally conductive adhesive foil, **W** = thermally conductive glue, **SB** = screw fixing

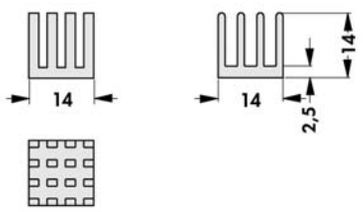
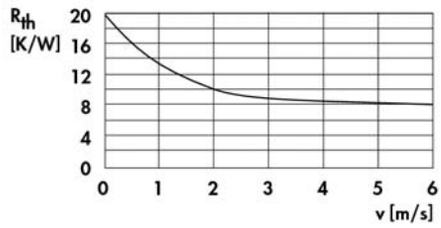
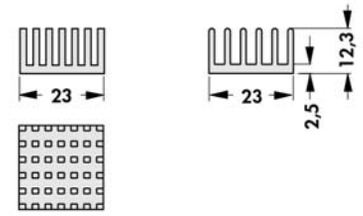
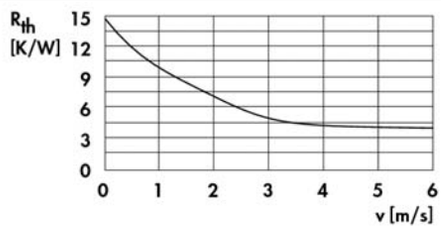
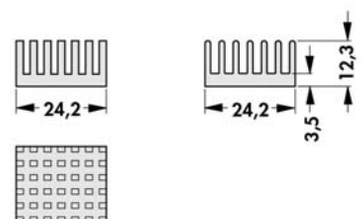
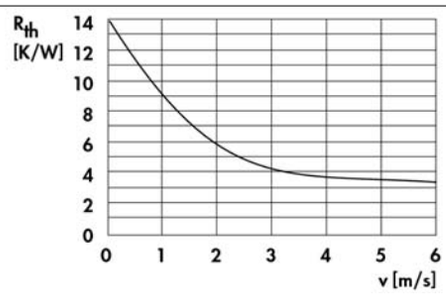
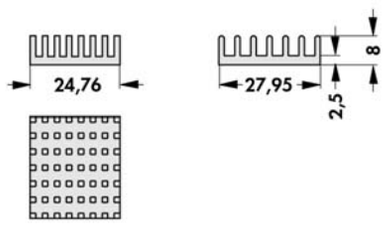
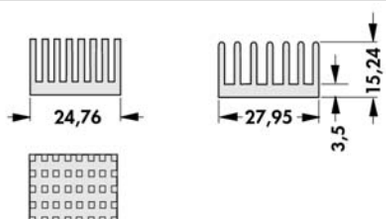
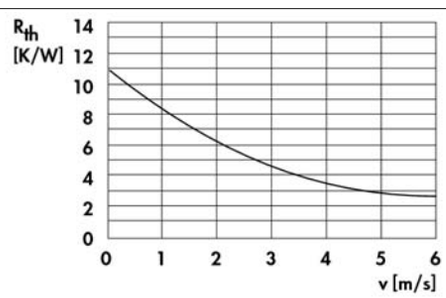
Technical data for fans with pulse output: → B 43
- pulse output for control of the alarm device circuit
- puls form is like rectangle with the triple frequency of rotation speed
- with blocked rotor the output signal can be L (0,8 v) or H (Vcc-1V)
- the pulse output must not be connected with GND or Vcc without a mutiplier (>10K)
- to prevent short circuits, do not isolate the used puls output

Heatsinks for BGA → **B 16 – 19**
Heatsinks for PGA → **B 10 – 15**
Heatsinks for microprocessors → **B 41**
Heatsinks for Pentium PRO → **B 41**
Heatsinks for P II-Mobile Module → **B 41**
Heatsinks for Pentium III-Xeon → **B 41**
Heatsinks for Pentium III-Xeon → **B 41 – 15**
Thermal conduct. foil WLFT 404/405 → **B 45**

Heatsinks for PGA

surface: black anodised

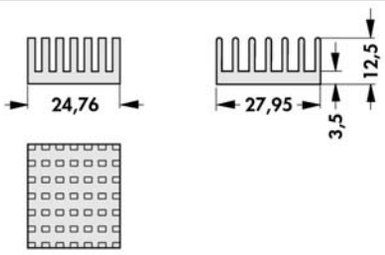
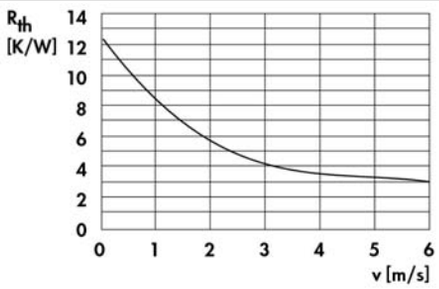
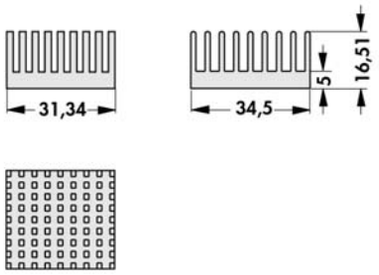
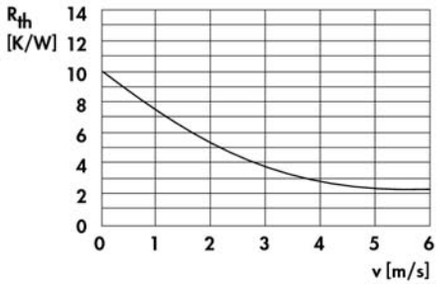
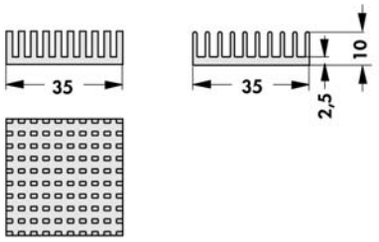
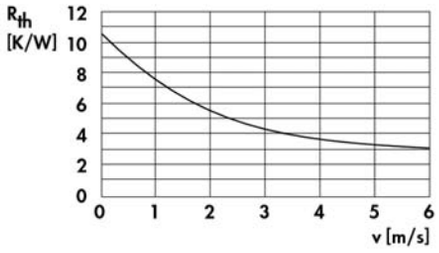
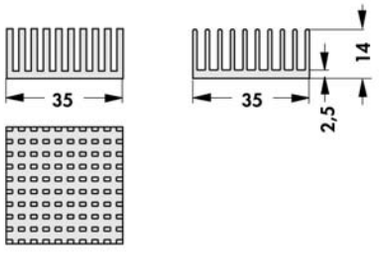
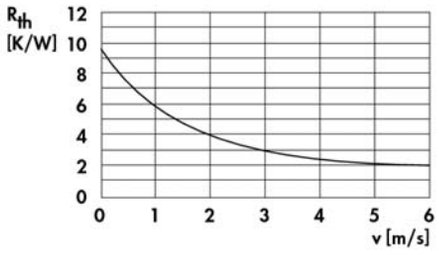
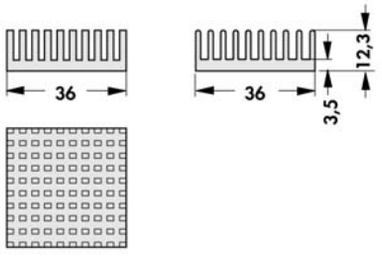
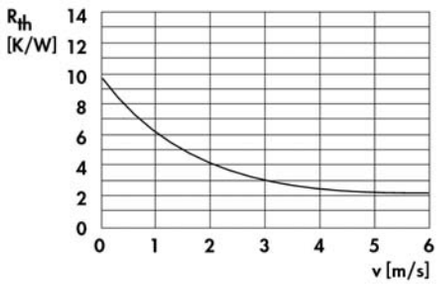
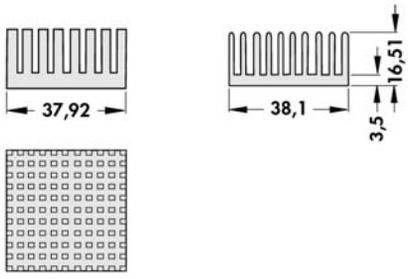
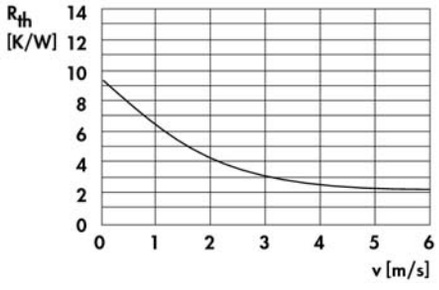


art. no.		
ICK PGA 6 x 6 x 14 WLF ... 14 x 14		
art. no.		
ICK PGA 8 x 8 x 12 WLF ... 23 x 23		
art. no.		
ICK PGA 9 x 9 WLF ... 24 x 24		
art. no.		
ICK PGA 11 x 11 x 8 WLF ... 24 x 27		
art. no.		
ICK PGA 11 x 11 WLF ... 24 x 27		

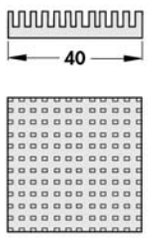
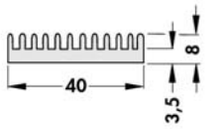
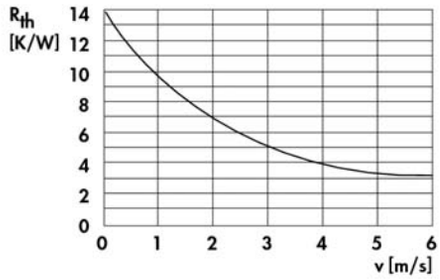
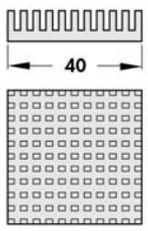
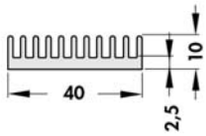
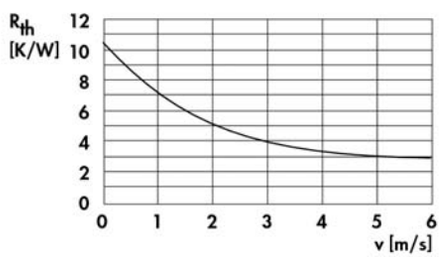
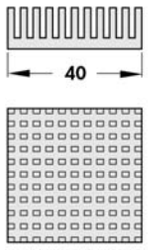
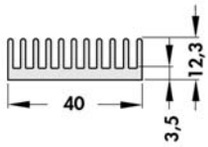
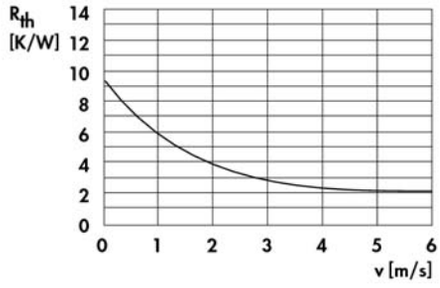
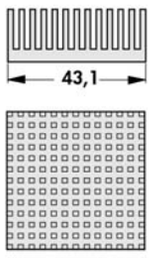
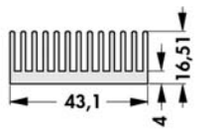
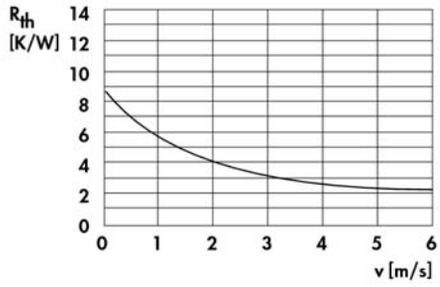
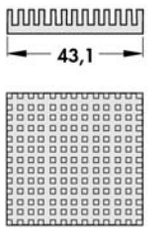
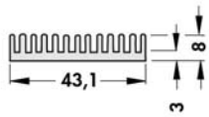
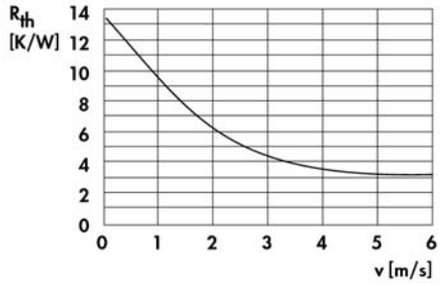
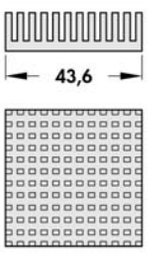
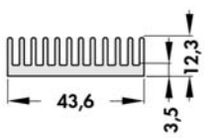
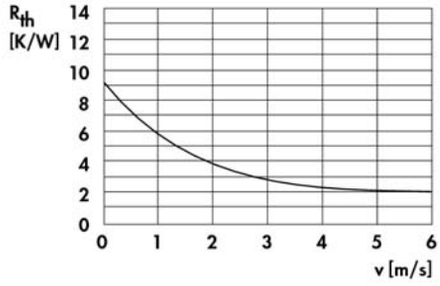
Thermal conduct. foil WLFT 404/405 → **E 5**
Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 9**
SMD-heatsinks → **B 38 – 40**
Mounting material for semiconduct. → **E 37 – 41**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

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Heatsinks for PGA

art. no.	
ICK PGA 11 x 11 x 12 WLF ... 24 x 27	 
art. no.	
ICK PGA 14 x 14 WLF ... 31 x 34	 
art. no.	
ICK PGA 14 x 14 x 10 WLF ... 35 x 35	 
art. no.	
ICK PGA 14 x 14 x 14 WLF ... 35 x 35	 
art. no.	
ICK PGA 14 x 14 x 12 WLF ... 36 x 36	 
art. no.	
ICK PGA 15 x 15 WLF ... 37 x 37	 

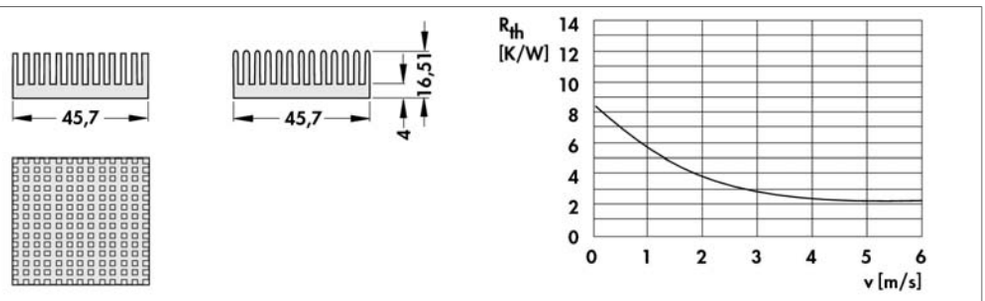
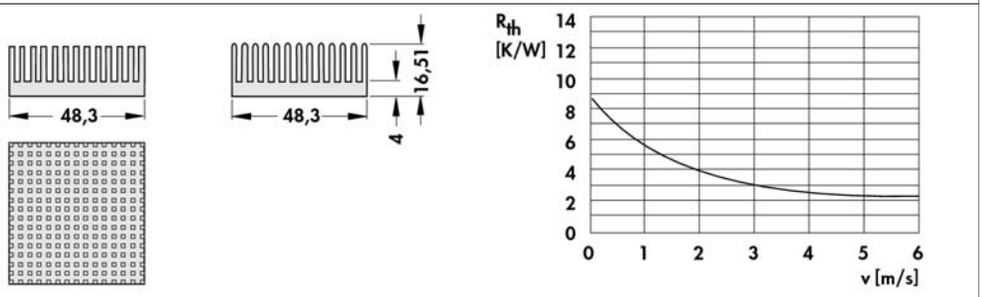
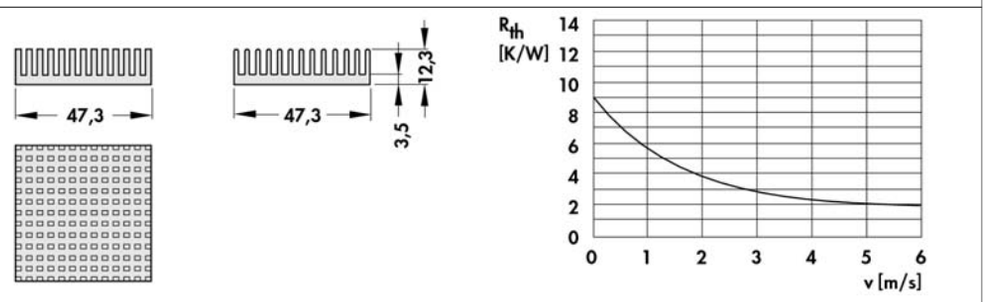
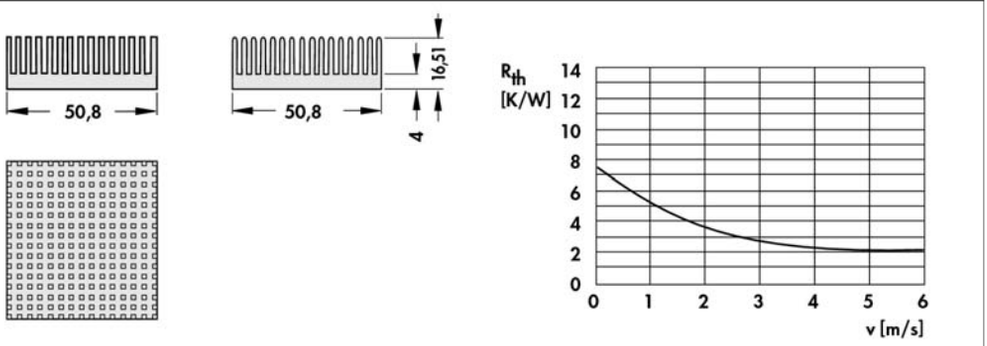
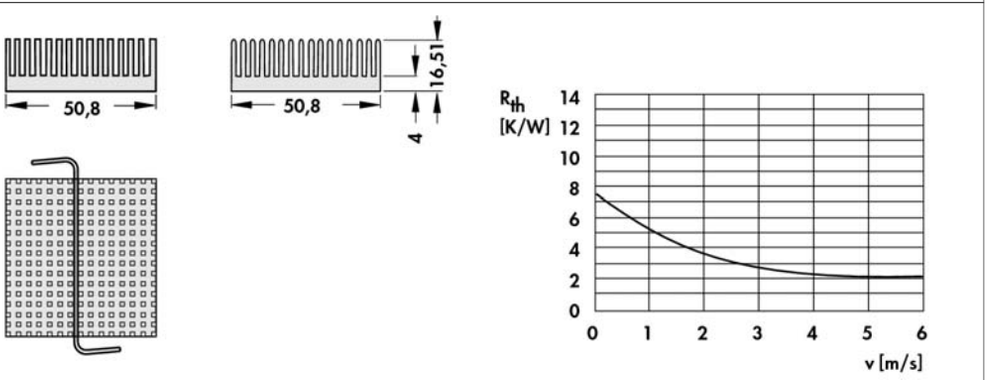
Heatsinks for PGA

art. no.			
ICK PGA 16 x 16 x 8 WLF ... 40 x 40			
art. no.			
ICK PGA 16 x 16 x 10 WLF ... 40 x 40			
art. no.			
ICK PGA 16 x 16 x 12 WLF ... 40 x 40			
art. no.			
ICK PGA 17 x 17 WLF ... 43 x 43			
art. no.			
ICK PGA 17 x 17 x 8 WLF ... 43 x 43			
art. no.			
ICK PGA 17 x 17 x 12 WLF ... 43 x 43			

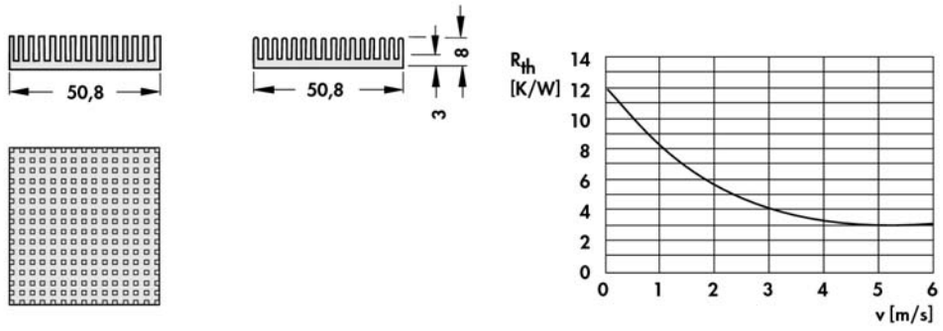
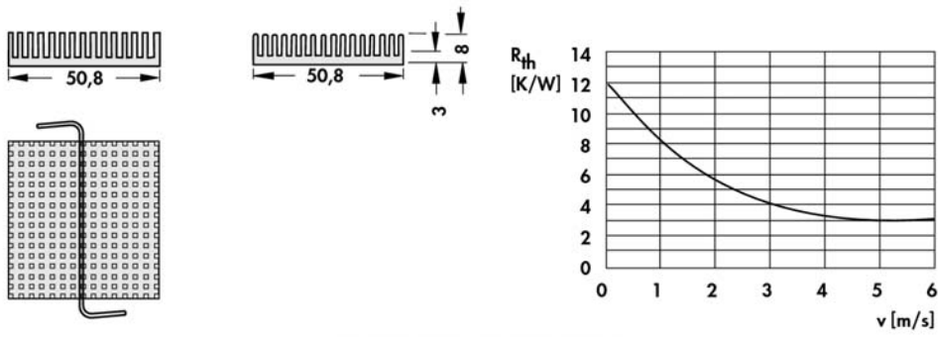
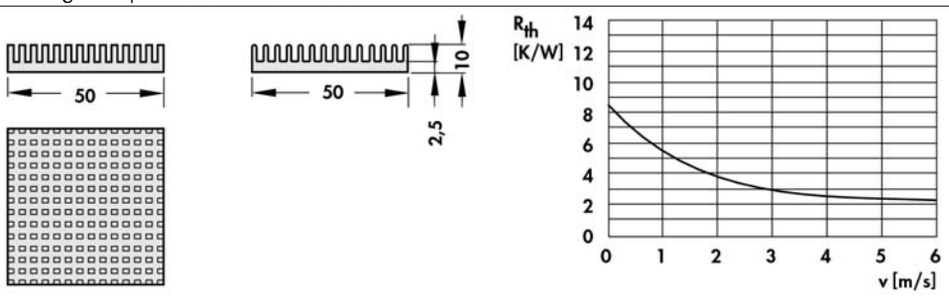
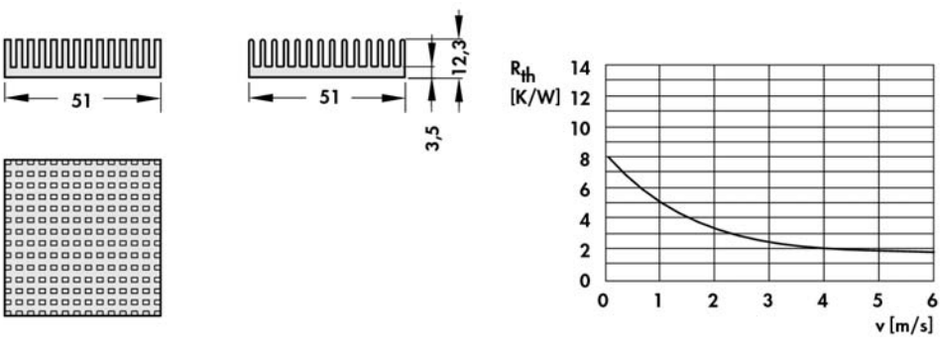
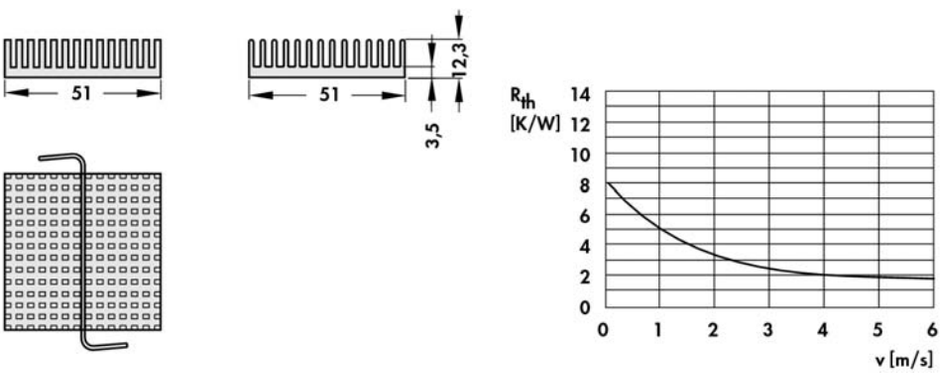
Thermal conduct. foil WLFT 404/405 → **E 5**
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Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

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Heatsinks for PGA

art. no.	
ICK PGA 18 x 18 WLF ... 45 x 45	
art. no.	
ICK PGA 19 x 19 WLF ... 48 x 48	
art. no.	
ICK PGA 19 x 19 x 12 WLF ... 47 x 47	
art. no.	
ICK PGA 20 x 20 WLF ... 50 x 50	
art. no.	
ICK PGA 20 x 20 K WLF ... 50 x 50	 with fixing clamp for socket 7 and socket 370

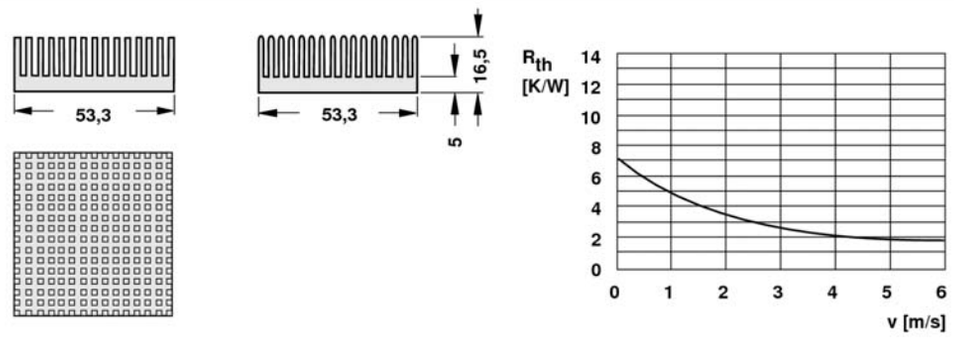
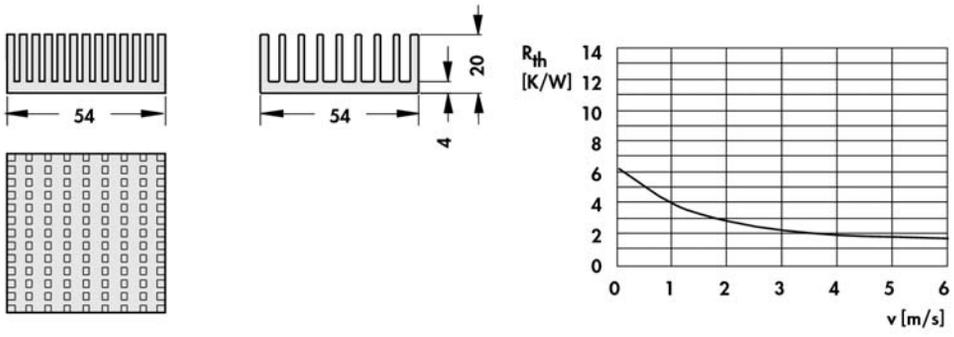
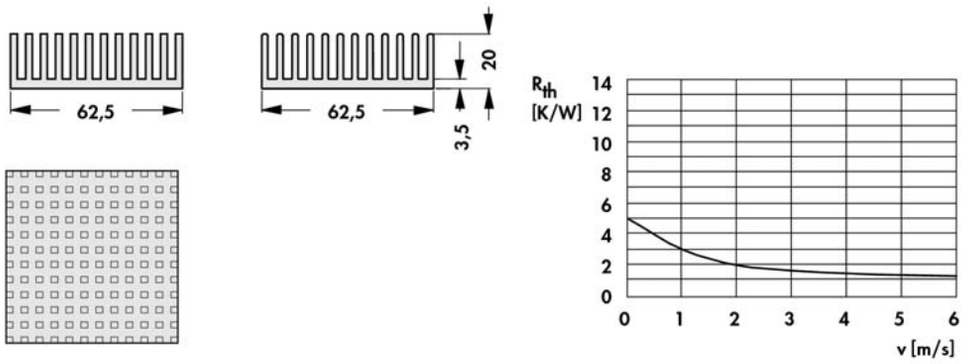
Heatsinks for PGA

art. no.	
ICK PGA 20 x 20 x 8 WLF ... 50 x 50	
art. no.	
ICK PGA 20 x 20 x 8 K WLF ... 50 x 50	 with fixing clamp for socket 7 and socket 370
art. no.	
ICK PGA 20 x 20 x 10 WLF ... 48 x 48	
art. no.	
ICK PGA 20 x 20 x 12 WLF ... 50 x 50	
art. no.	
ICK PGA 20 x 20 x 12 K WLF ... 50 x 50	 with fixing clamp for socket 7 and socket 370

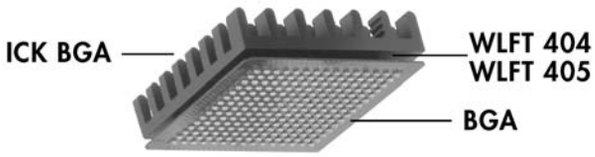
Thermal conduct. foil WLFT 404/405 → **E 5**
Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 9**
SMD-heatsinks → **B 38 – 40**
Mounting material for semiconduct. → **E 37 – 41**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

fischer elektronik

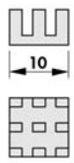
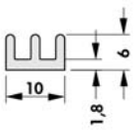
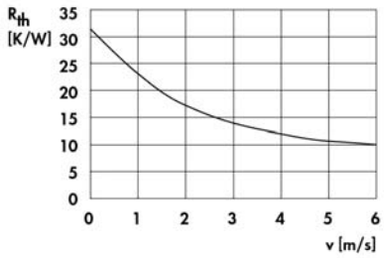
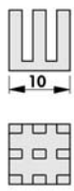
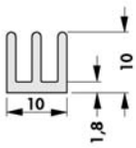
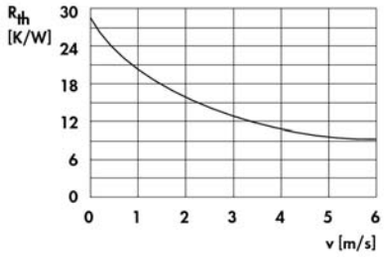
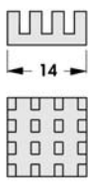
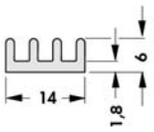
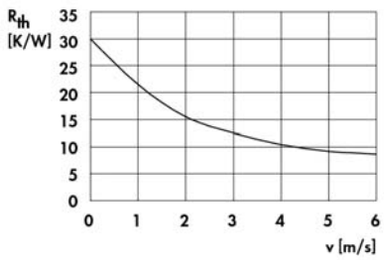
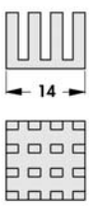
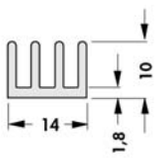
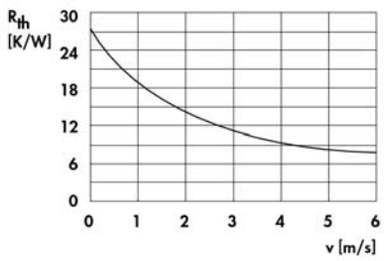
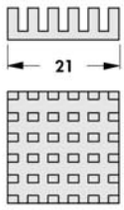
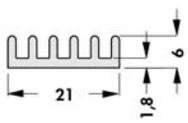
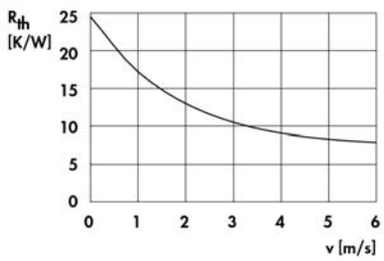
Heatsinks for PGA

art. no.	
ICK PGA 21 x 21 WLF ... 53 x 53	
art. no.	
ICK PGA 22 x 22 WLF ... 54 x 54	
art. no.	
ICK PGA 25 x 25 WLF ... 62 x 62	

Heatsinks for BGAs

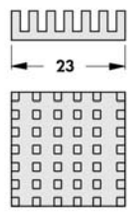
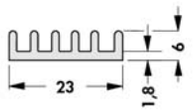
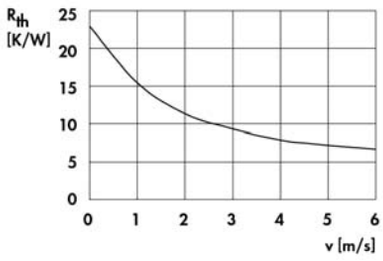
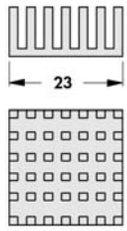
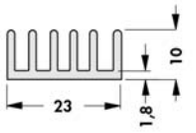
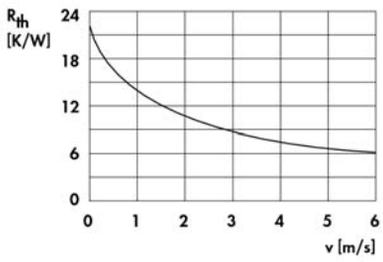
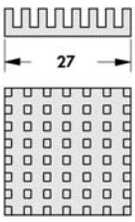
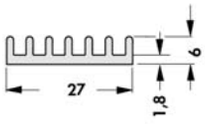
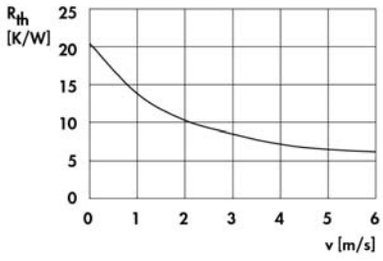
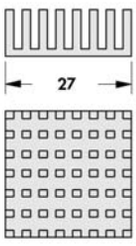
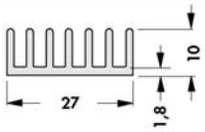
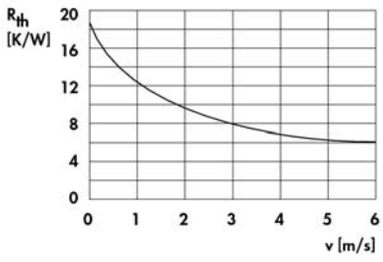
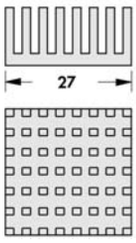
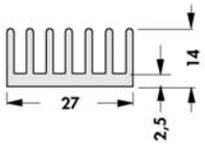
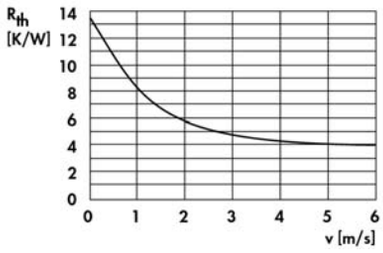
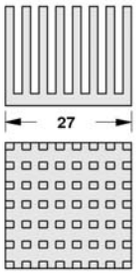
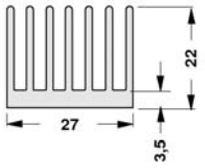
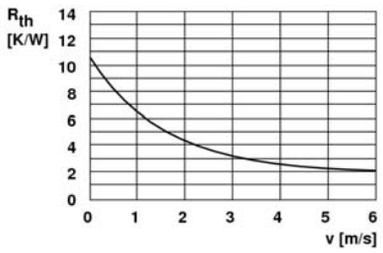


– particularly suited for **B**all **G**rid **A**rrays
– heatsink dimensions match the respective BGA-type
– can be glued directly on the BGA component
surface: black anodised

art. no.			
ICK BGA 10 x 10 WLF ... 10 x 10			
art. no.			
ICK BGA 10 x 10 x 10 WLF ... 10 x 10			
art. no.			
ICK BGA 14 x 14 WLF ... 14 x 14			
art. no.			
ICK BGA 14 x 14 x 10 WLF ... 14 x 14			
art. no.			
ICK BGA 21 x 21 WLF ... 21 x 21			

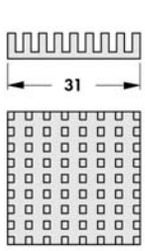
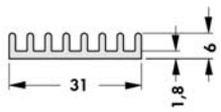
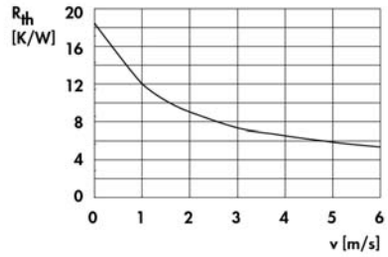
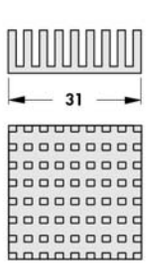
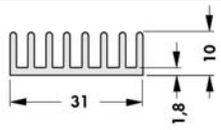
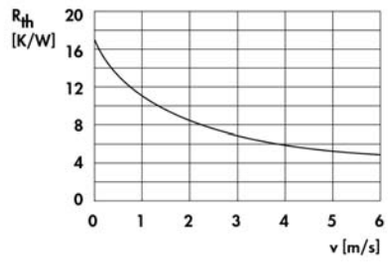
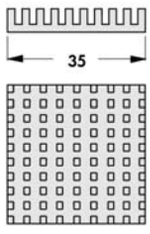
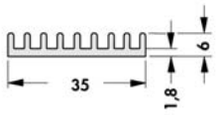
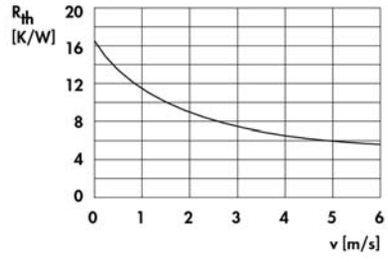
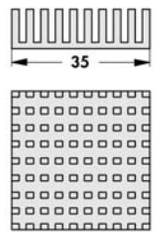
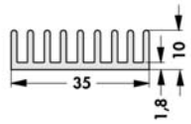
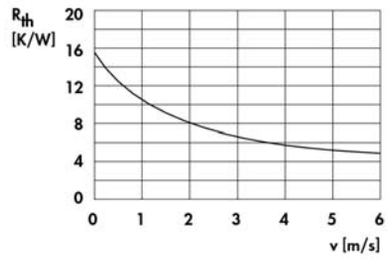
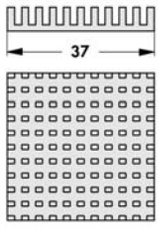
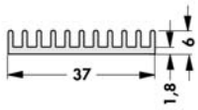
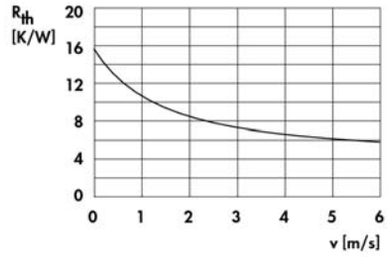
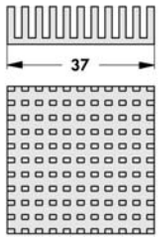
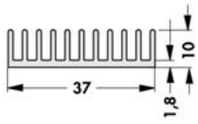
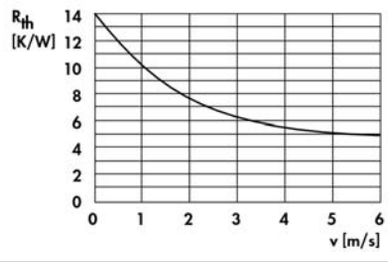
Thermal conduct. foil WLFT 404/405 → **E 5**
Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 7**
SMD-heatsinks → **B 38 – 40**
Mounting material for semiconduct. → **E 37 – 41**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

Heatsinks for BGAs

art. no.			
ICK BGA 23 x 23 WLF ... 23 x 23			
art. no.			
ICK BGA 23 x 23 x 10 WLF ... 23 x 23			
art. no.			
ICK BGA 27 x 27 WLF ... 27 x 27			
art. no.			
ICK BGA 27 x 27 x 10 WLF ... 27 x 27			
art. no.			
ICK BGA 27 x 27 x 14 WLF ... 27 x 27			
art. no.			
ICK BGA 27 x 27 x 22 WLF ... 27 x 27			

Thermal conduct. foil WLFT 404/405 → E 5
Thermal conductive glue → E 15
Thermal conductive paste → E 13
Processor overview → B 2 - 7
SMD-heatsinks → B 38 – 40
Mounting material for semiconduct. → E 37 – 41
Hole pattern → A 21
Technical introduction → A 2 - 7

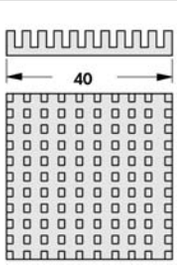
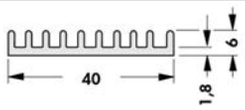
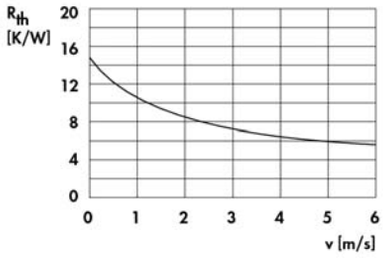
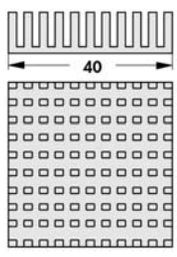
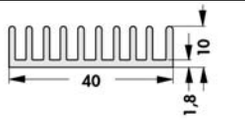
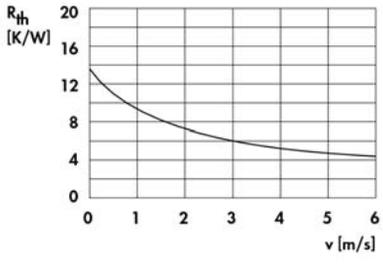
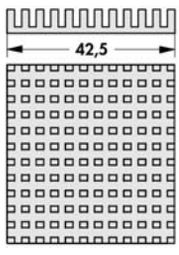
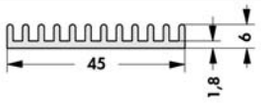
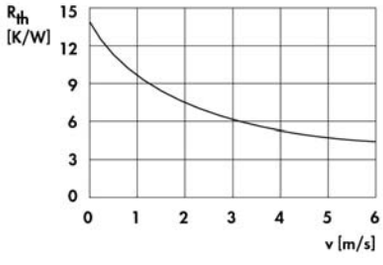
Heatsinks for BGAs

art. no.			
ICK BGA 31 x 31 WLF ... 31 x 31			
art. no.			
ICK BGA 31 x 31 x 10 WLF ... 31 x 31			
art. no.			
ICK BGA 35 x 35 WLF ... 35 x 35			
art. no.			
ICK BGA 35 x 35 x 10 WLF ... 35 x 35			
art. no.			
ICK BGA 37 x 37 x 6 WLF ... 37 x 37			
art. no.			
ICK BGA 37 x 37 x 10 WLF ... 37 x 37			

Thermal conduct. foil WLFT 404/405 → **E 5**
Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 7**
SMD-heatsinks → **B 38 – 40**
Mounting material for semiconduct. → **E 37 – 41**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

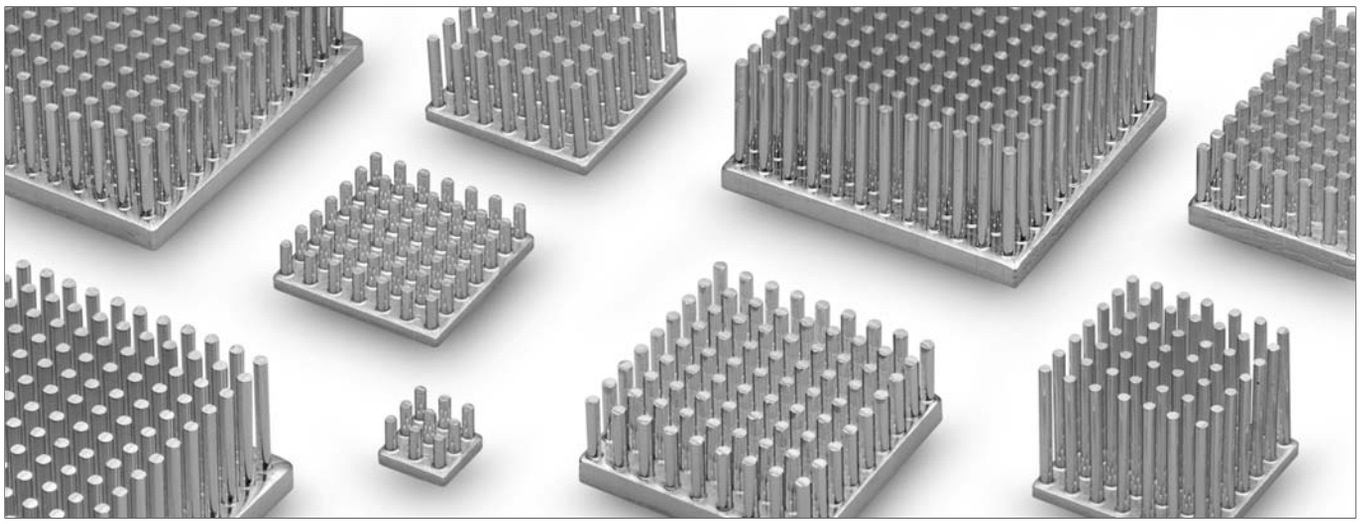
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Heatsinks for BGAs

art. no.			
ICK BGA 40 x 40 WLF ... 40 x 40			
art. no.			
ICK BGA 40 x 40 x 10 WLF ... 40 x 40			
art. no.			
ICK BGA 42,5 x 45 WLF ... 42,5 x 45			

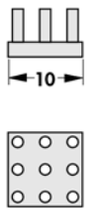
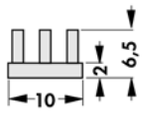
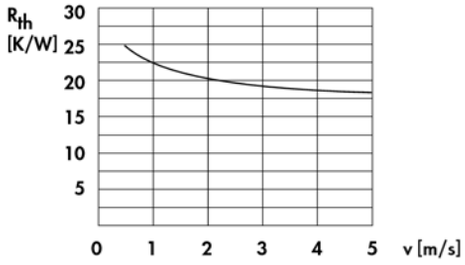
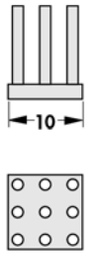
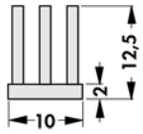
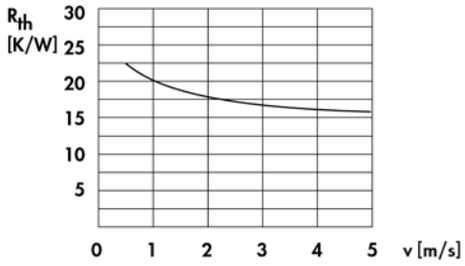
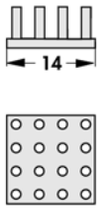
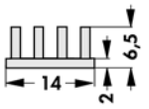
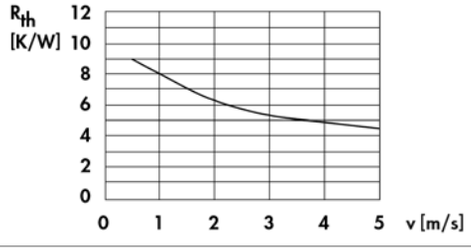
Thermal conduct. foil WLFT 404/405	→ E 5	SMD-heatsinks	→ B 38 – 40
Thermal conductive glue	→ E 15	Mounting material for semiconduct.	→ E 37 – 41
Thermal conductive paste	→ E 13	Hole pattern	→ A 21
Processor overview	→ B 2 - 7	Technical introduction	→ A 2 - 7

Pin heatsinks



– arrangement and number of pins for optimum air flow
– suitable for forced and free convention
– excellent thermal conductivity by the alloy material (Al99,5; 220 W/mK) and homogeneous arrangement of materials
– constant heat distribution in the base and the pins, in the direction of heat flow
– low weight achieved by optimised geometry
– Components fastened using glue, adhesive foil or clamps

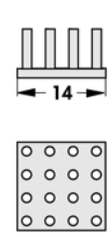
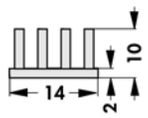
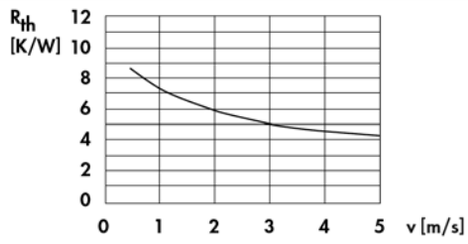
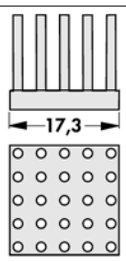
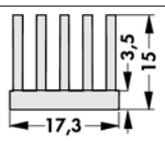
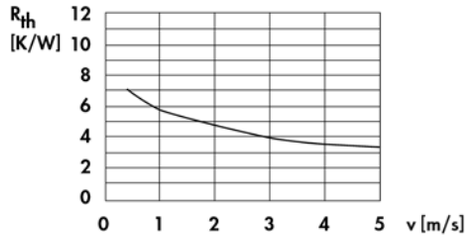
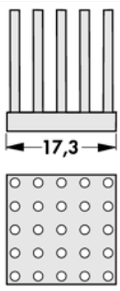
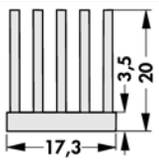
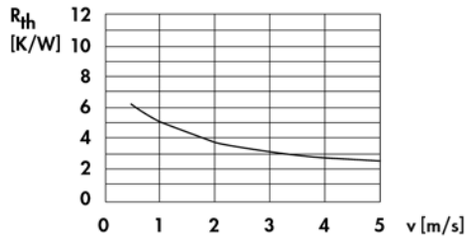
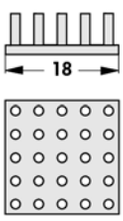
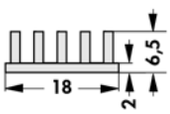
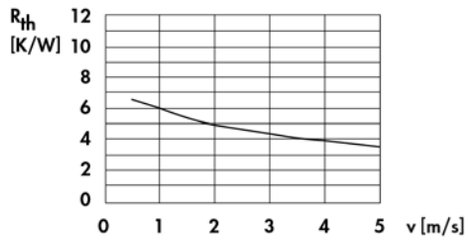
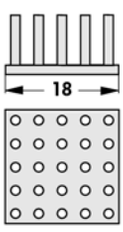
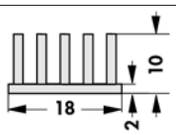
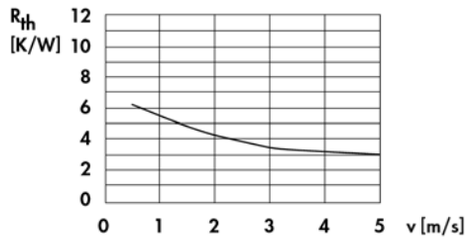
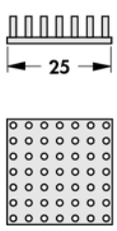
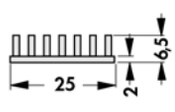
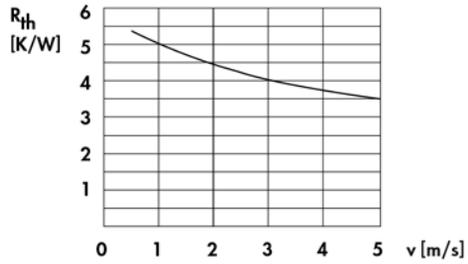
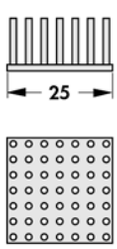
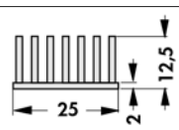
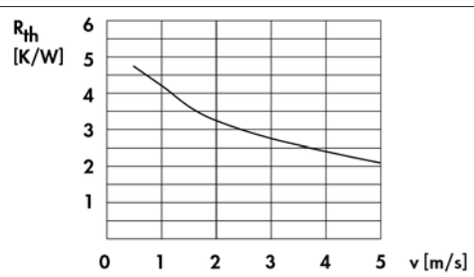
customer-specific modifications and special designs; other pin-lengths and surfaces on request
surface: Al-natural

art. no.			
ICK S 10 x 10 x 6,5 WLF ... 10 x 10 weight: 1 g			
art. no.			
ICK S 10 x 10 x 12,5 WLF ... 10 x 10 weight: 1.3 g			
art. no.			
ICK S 14 x 14 x 6,5 WLF ... 14 x 14 weight: 1.5 g			

Thermal conduct. foil WLFT 404/405 → **E 5**
Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 7**
SMD-heatsinks → **B 38 – 40**
Mounting material for semiconduct. → **E 37 – 41**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

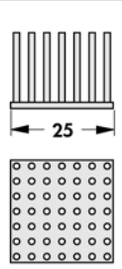
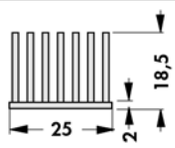
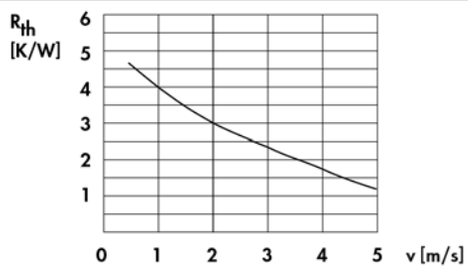
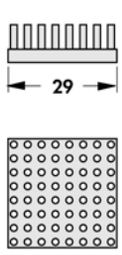
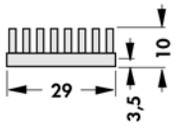
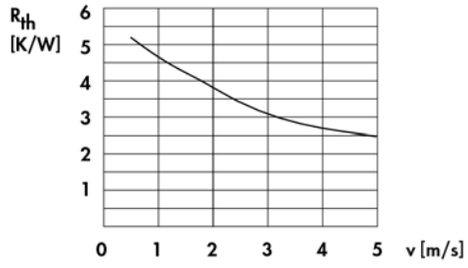
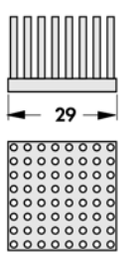
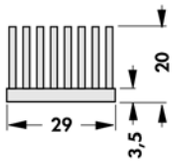
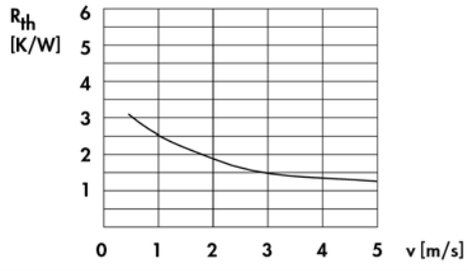
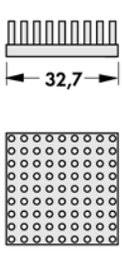
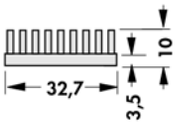
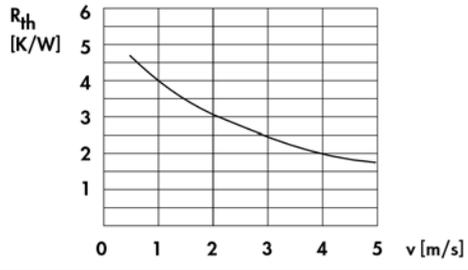
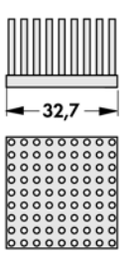
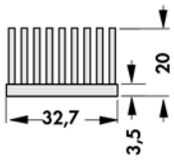
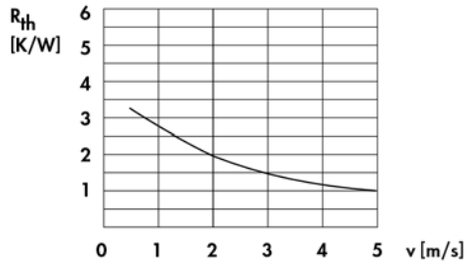
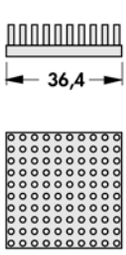
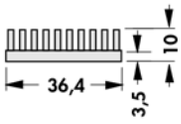
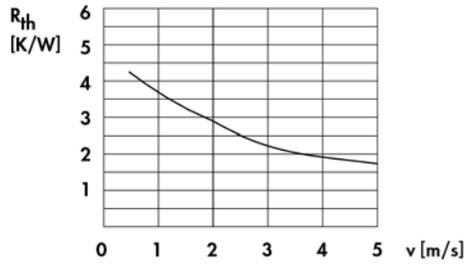
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Pin heatsinks

art. no.			
ICK S 14 x 14 x 10 WLF ... 14 x 14 weight: 1.9 g			
art. no.			
ICK S 17 x 17 x 15 WLF ... 17 x 17 weight: 4.7 g			
art. no.			
ICK S 17 x 17 x 20 WLF ... 17 x 17 weight: 5.6 g			
art. no.			
ICK S 18 x 18 x 6,5 WLF ... 18 x 18 weight: 2.5 g			
art. no.			
ICK S 18 x 18 x 10 WLF ... 18 x 18 weight: 3.1 g			
art. no.			
ICK S 25 x 25 x 6,5 WLF ... 25 x 25 weight: 4 g			
art. no.			
ICK S 25 x 25 x 12,5 WLF ... 25 x 25 weight: 6 g			

Thermal conduct. foil WLFT 404/405 → **E 5**
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Thermal conductive paste → **E 13**
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SMD-heatsinks → **B 38 – 40**
Mounting material for semiconduct. → **E 37 – 41**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

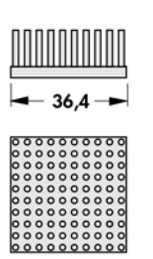
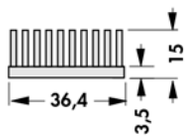
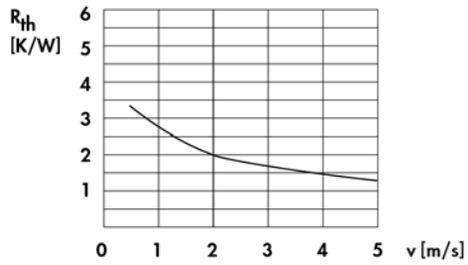
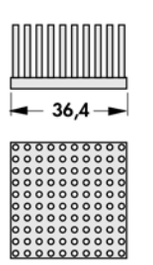
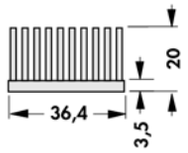
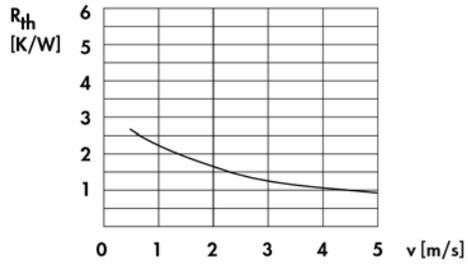
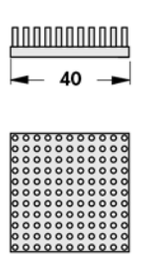
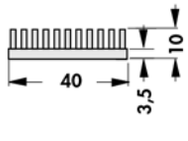
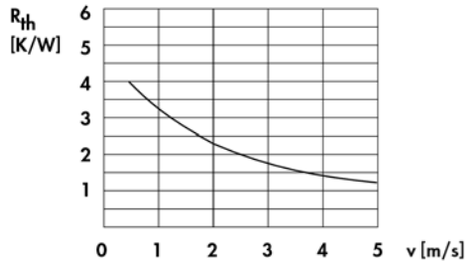
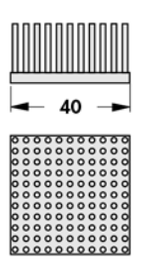
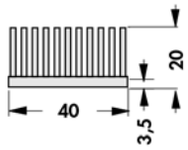
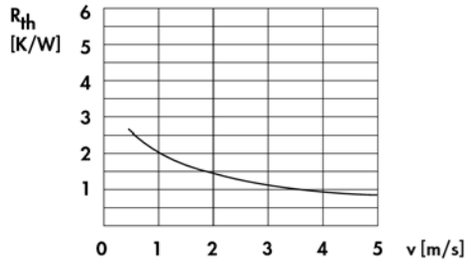
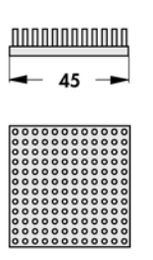
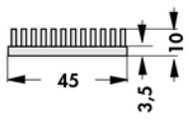
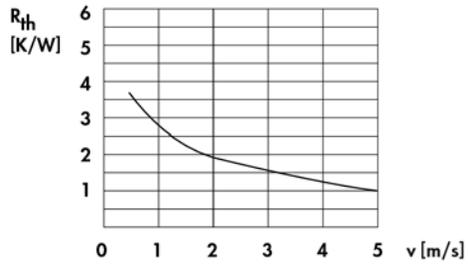
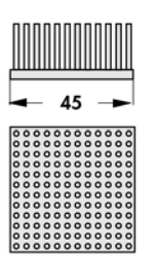
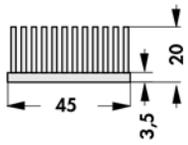
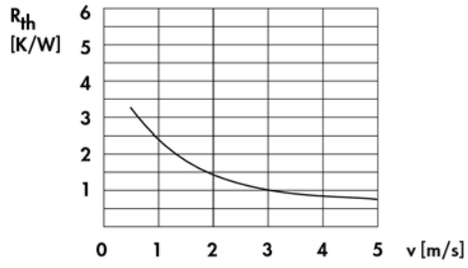
Pin heatsinks

art. no.			
ICK S 25 x 25 x 18,5 WLF ... 25 x 25 weight: 7 g			
art. no.			
ICK S 29 x 29 x 10 WLF ... 29 x 29 weight: 11 g			
art. no.			
ICK S 29 x 29 x 20 WLF ... 29 x 29 weight: 15 g			
art. no.			
ICK S 32 x 32 x 10 WLF ... 32 x 32 weight: 14 g			
art. no.			
ICK S 32 x 32 x 20 WLF ... 32 x 32 weight: 19 g			
art. no.			
ICK S 36 x 36 x 10 WLF ... 36 x 36 weight: 17 g			

Thermal conduct. foil WLFT 404/405 → **E 5**
Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 7**
SMD-heatsinks → **B 38 – 40**
Mounting material for semiconduct. → **E 37 – 41**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

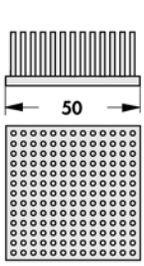
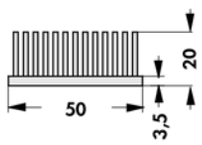
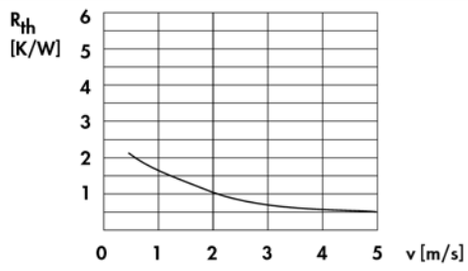
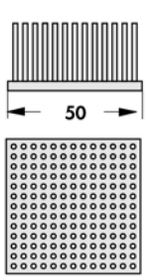
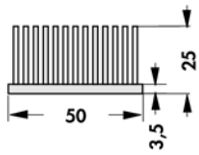
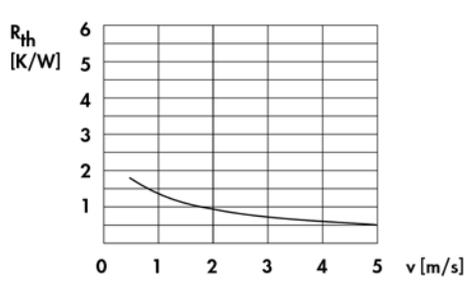
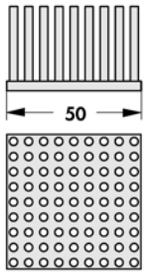
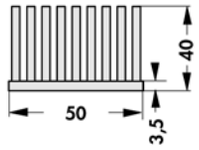
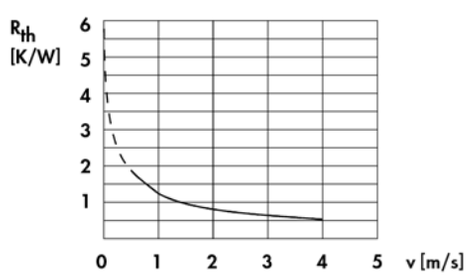
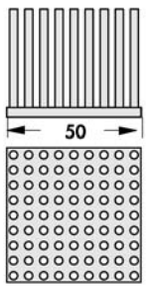
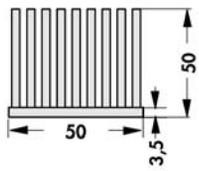
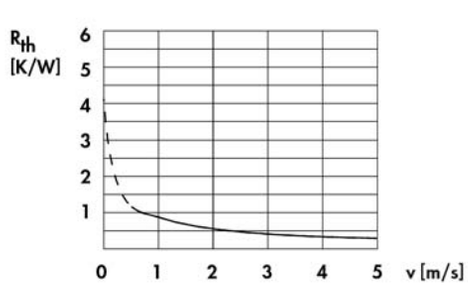
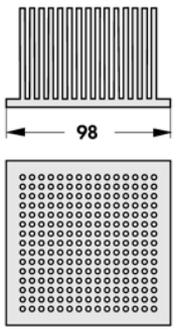
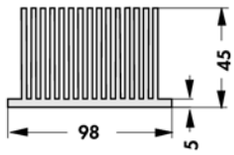
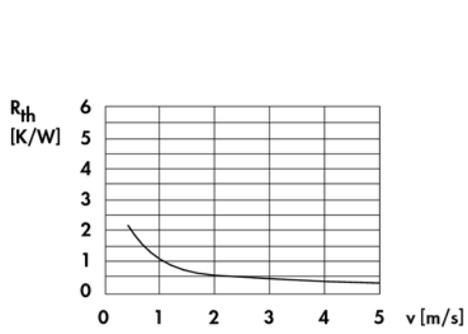
fischer elektronik

Pin heatsinks

art. no.			
ICK S 36 x 36 x 15 WLF ... 36 x 36 weight: 20 g			
art. no.			
ICK S 36 x 36 x 20 WLF ... 36 x 36 weight: 24 g			
art. no.			
ICK S 40 x 40 x 10 WLF ... 40 x 40 weight: 21 g			
art. no.			
ICK S 40 x 40 x 20 WLF ... 40 x 40 weight: 29 g			
art. no.			
ICK S 45 x 45 x 10 WLF ... 45 x 45 weight: 26 g			
art. no.			
ICK S 45 x 45 x 20 WLF ... 45 x 45 weight: 36 g			

Thermal conduct. foil WLFT 404/405 → E 5
Thermal conductive glue → E 15
Thermal conductive paste → E 13
Processor overview → B 2 - 7
SMD-heatsinks → B 38 – 40
Mounting material for semiconduct. → E 37 – 41
Hole pattern → A 21
Technical introduction → A 2 - 7

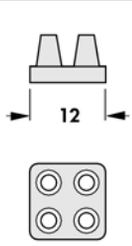
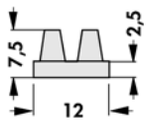
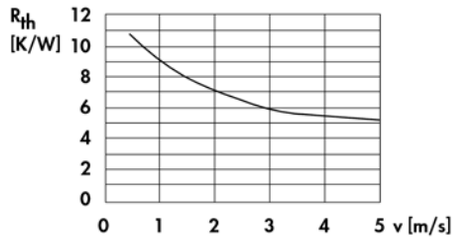
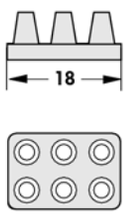
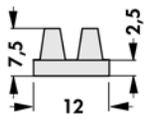
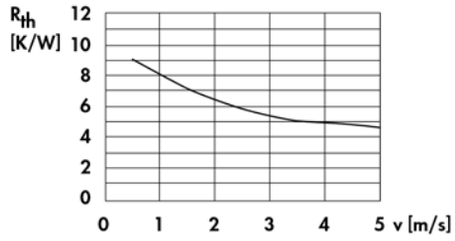
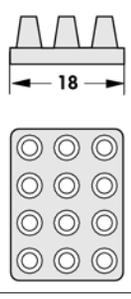
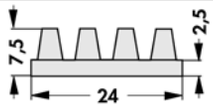
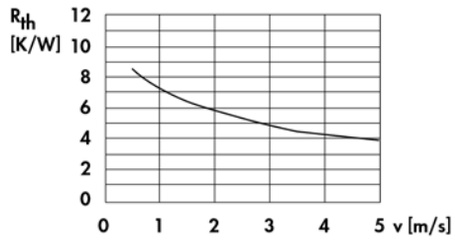
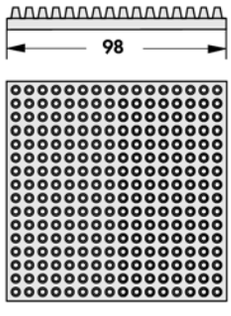
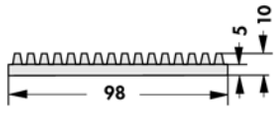
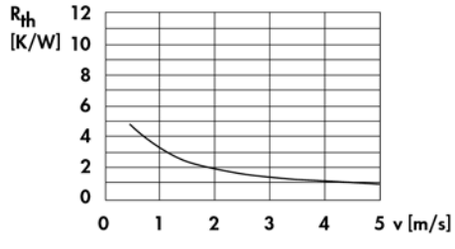
Pin heatsinks

art. no.			
ICK S 50 x 50 x 20 WLF ... 50 x 50 weight: 43 g			
art. no.			
ICK S 50 x 50 x 25 WLF ... 50 x 50 weight: 49 g			
art. no.			
ICK S 50 x 50 x 40 WLF ... 50 x 50 weight: 80.05 g			
art. no.			
ICK S 50 x 50 x 50 WLF ... 50 x 50 weight: 95.51 g			
art. no.			
ICK S 98 x 98 x 45 WLF ... 98 x 98 weight: 301.3 g			

Thermal conduct. foil WLFT 404/405 → **E 5**
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Pin heatsinks

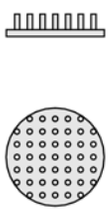
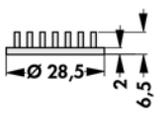
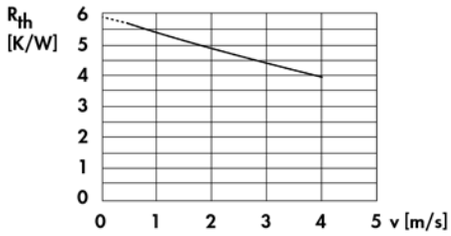
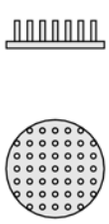
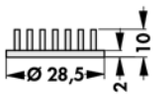
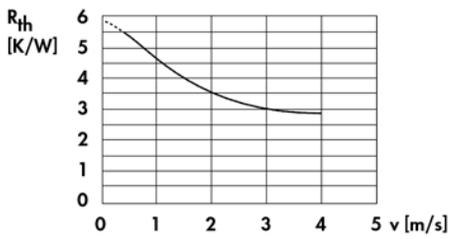
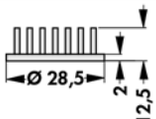
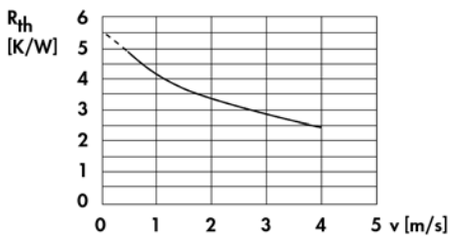
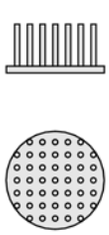
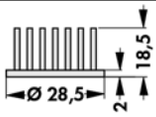
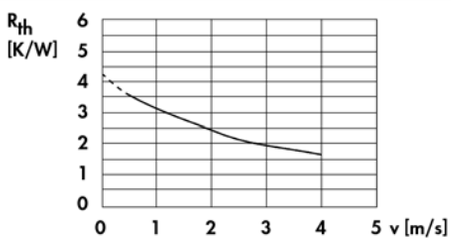
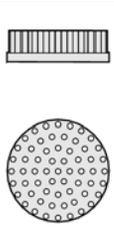
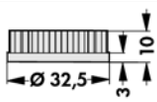
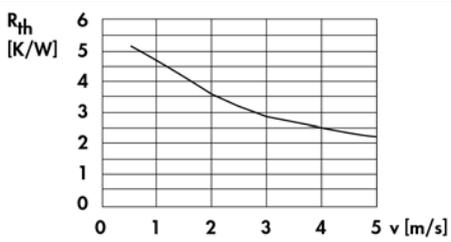
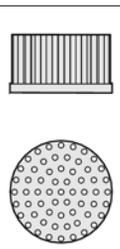
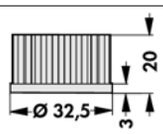
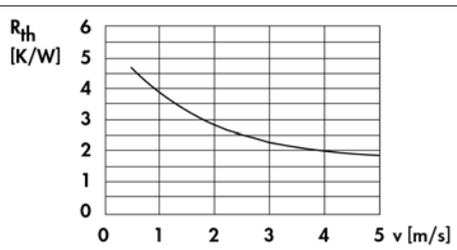
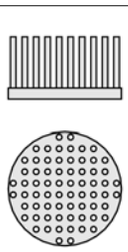
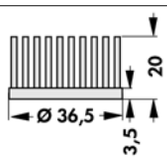
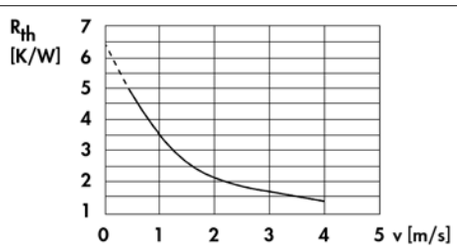
Dome

art. no.			
ICK S D 12 x 12 x 7,5 WLF ... 12 x 12 weight: 1.8 g			
art. no.			
ICK S D 18 x 12 x 7,5 WLF ... 12 x 18 weight: 2.7 g			
art. no.			
ICK S D 24 x 18 x 7,5 WLF ... 18 x 24 weight: 4.4 g			
art. no.			
ICK S D 98 x 98 x 10 WLF ... 98 x 98 weight: 154 g			

Thermal conduct. foil WLFT 404/405 → E 5
Thermal conductive glue → E 15
Thermal conductive paste → E 13
Processor overview → B 2 - 7
SMD-heatsinks → B 38 – 40
Mounting material for semiconduct. → E 37 – 41
Hole pattern → A 21
Technical introduction → A 2 - 7

Pin heatsinks

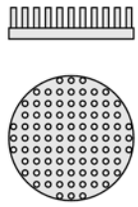
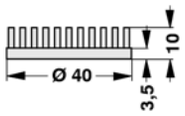
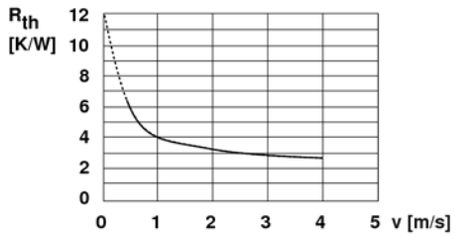
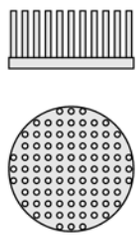
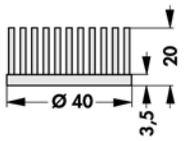
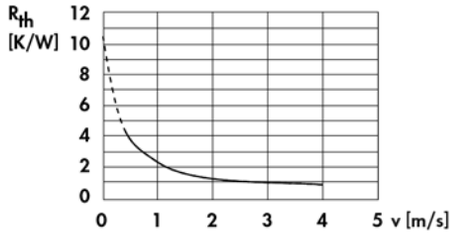
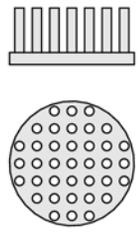
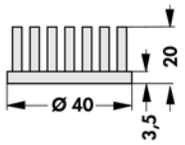
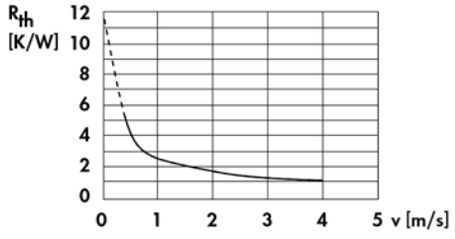
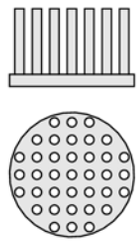
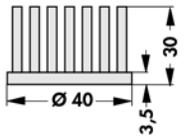
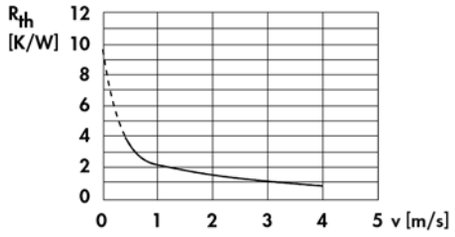
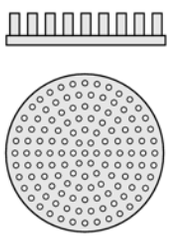
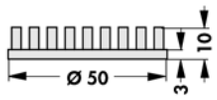
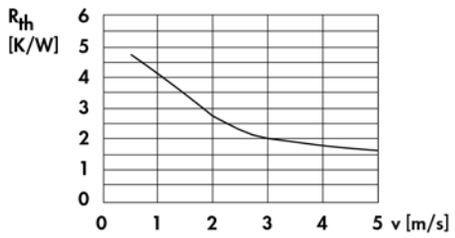
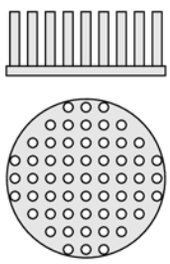
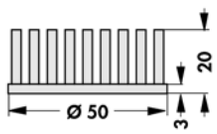
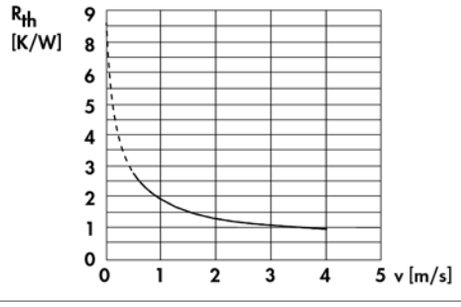
Round

art. no.			
ICK S R 28,5 x 6,5 WLF ... D 28,5 weight: 4.41 g			
art. no.			
ICK S R 28,5 x 10 WLF ... D 28,5 weight: 5.16 g			
art. no.			
ICK S R 28,5 x 12,5 WLF ... D 28,5 weight: 5.7 g			
art. no.			
ICK S R 28,5 x 18,5 WLF ... D 28,5 weight: 6.98 g			
art. no.			
ICK S R 32,5 x 10 WLF ... D 32 weight: 9.7 g			
art. no.			
ICK S R 32,5 x 20 WLF ... D 32 weight: 13.8 g			
art. no.			
ICK S R 36,5 x 20 WLF ... D 36,5 weight: 17.59 g			

Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
SMD-heatsinks → **B 38 – 40**
Thermal conduct. foil WLFT 404/405 → **E 5**
Mounting material for semiconduct. → **E 37 – 41**
Thermal conduct. foil WLFT 404/405 → **E 5**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

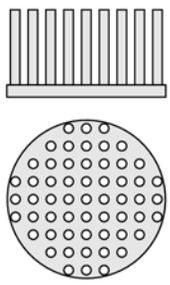
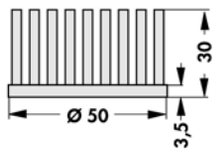
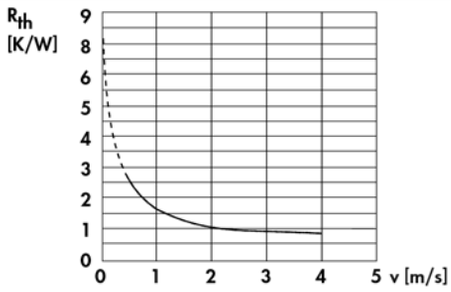
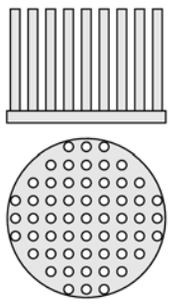
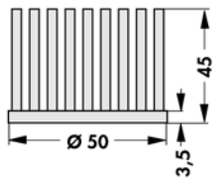
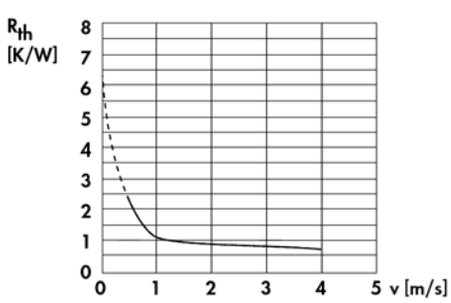
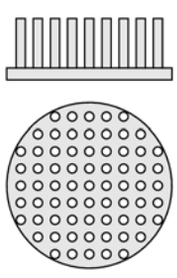
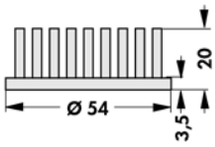
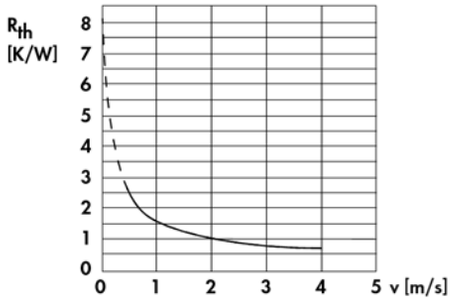
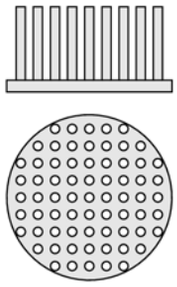
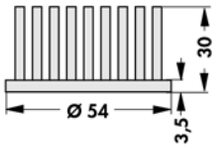
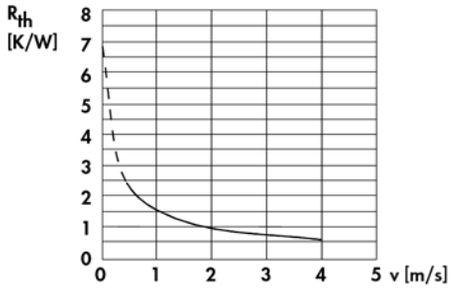
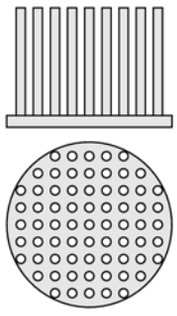
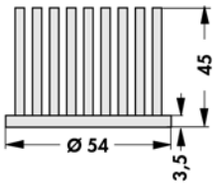
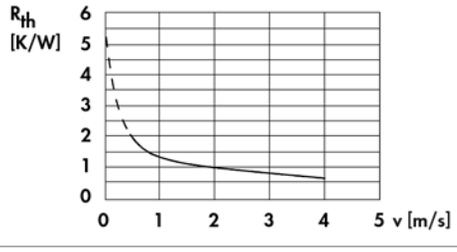
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Pin heatsinks

art. no.			
ICK S R 40 x 10 WLF ... D 40 weight: 15.85 g			
ICK S R 40 x 20 WLF ... D 40 weight: 21.96 g			
ICK S R A 40 x 20 WLF ... D 40 weight: 22.18 g			
ICK S R 40 x 30 WLF ... D 40 weight: 29.24 g			
ICK S R 50 x 10 WLF ... D 50 weight: 22 g			
ICK S R 50 x 20 WLF ... D 50 weight: 34.39 g			

Thermal conductive glue → E 15
Thermal conductive paste → E 13
SMD-heatsinks → B 38 – 40
Thermal conduct. foil WLFT 404/405 → E 5
Mounting material for semiconduct. → E 37 – 41
Thermal conduct. foil WLFT 404/405 → E 5
Hole pattern → A 21
Technical introduction → A 2 - 7

Pin heatsinks

art. no.			
ICK S R 50 x 30 WLF ... D 50 weight: 45.28 g			
art. no.			
ICK S R 50 x 45 WLF ... D 50 weight: 61.59 g			
art. no.			
ICK S R 54 x 20 WLF ... D 54 weight: 40.94 g			
art. no.			
ICK S R 54 x 30 WLF ... D 54 weight: 54.11 g			
art. no.			
ICK S R 54 x 45 WLF ... D 54 weight: 73.86 g			

Thermal conductive glue → **E 15**
Thermal conductive paste → **E 13**
SMD-heatsinks → **B 38 – 40**
Thermal conduct. foil WLFT 404/405 → **E 5**

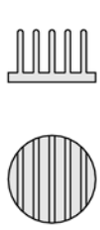
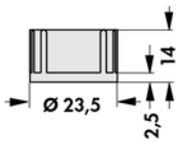
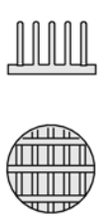
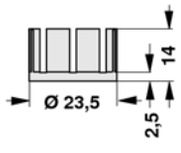
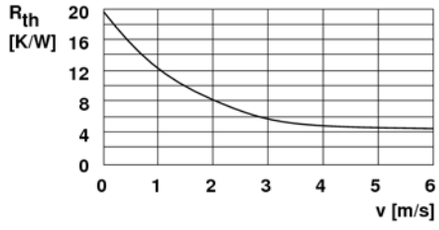
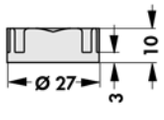
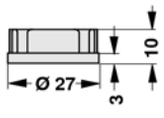
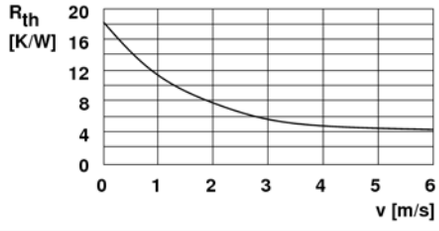
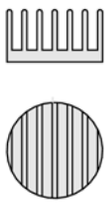
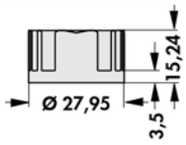
Mounting material for semiconduct. → **E 37 – 41**
Thermal conduct. foil WLFT 404/405 → **E 5**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

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Heatsinks for LEDs

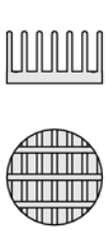
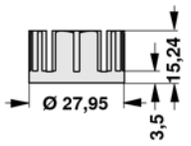
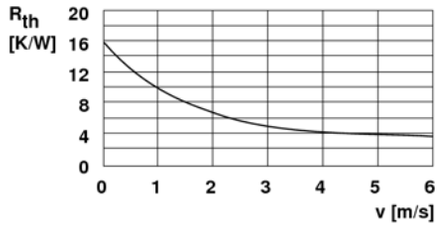
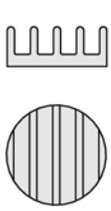
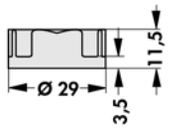
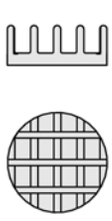
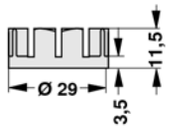
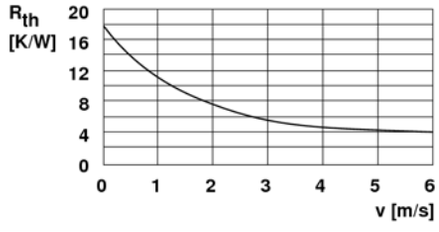
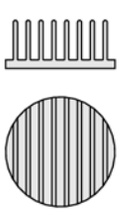
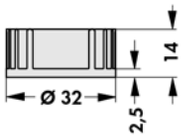
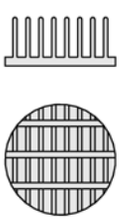
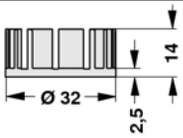
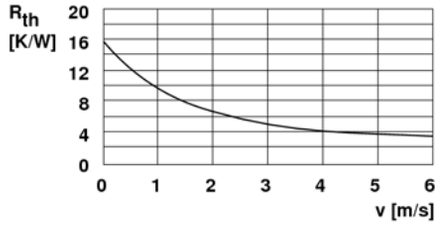
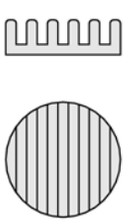
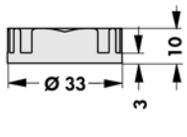
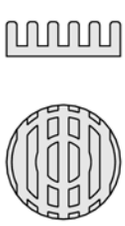
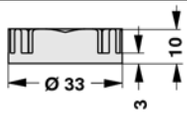
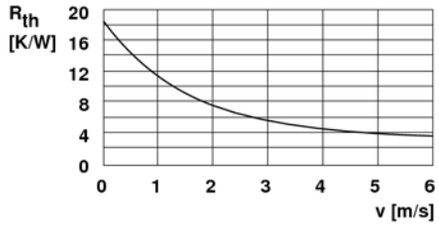


– suitable for free or forced convection
– heat sink dimensions are fitted to the respective LED typ
– simple mounting by using thermally conductive adhesive foil, glue or screw mounting
– specific versions on customer´s request
– special design, surfaces and modification to customer specification on request
surface: black anodised

art. no.		
ICK LED R 23,5 x 14 WLF ... D 23	 	R_{th} = 18,58 K/W
art. no.		
ICK LED R 23,5 x 14 G WLF ... D 23	 	
art. no.		
ICK LED R 27 x 10 WLF ... D 27	 	R_{th} = 17,69 K/W
art. no.		
ICK LED R 27 x 10 G WLF ... D 27	 	
art. no.		
ICK LED R 28 x 15 WLF ... D 28	 	R_{th} = 15,24 K/W

Mounting material for semiconduct. → **E 37 – 41**
SMD-heatsinks → **B 38 – 40**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 8**
Thermally conductive material → **E 15**
Thermal conduct. foil WLFT 404/405 → **E 5**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

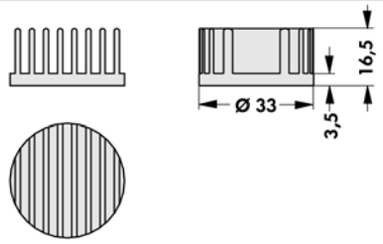
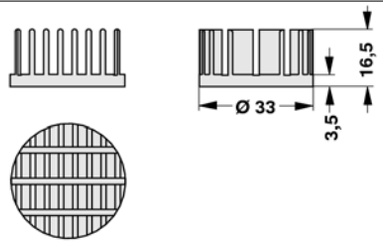
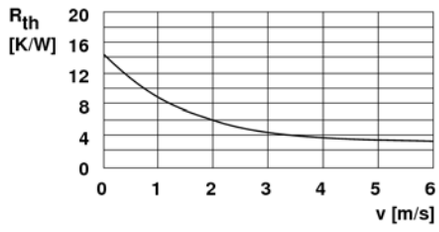
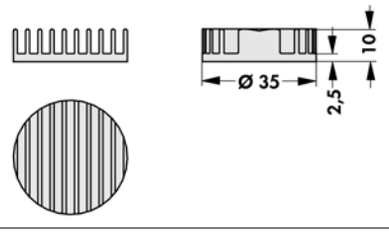
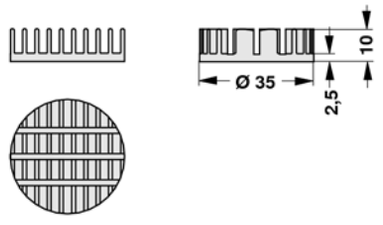
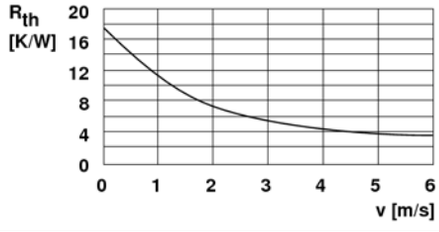
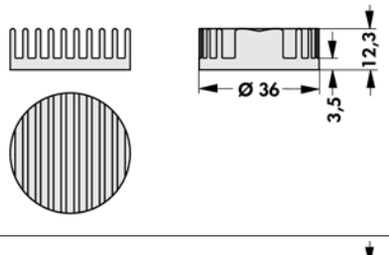
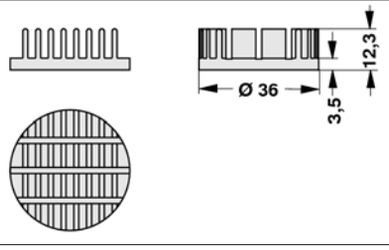
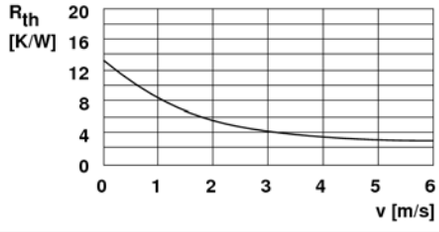
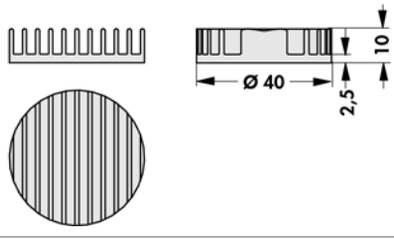
Heatsinks for LEDs

art. no.			
ICK LED R 28 x 15 G WLF ... D 28			
art. no.			
ICK LED R 29 x 11,5 WLF ... D 29			R_{th} = 17,26 K/W
art. no.			
ICK LED R 29 x 11,5 G WLF ... D 29			
art. no.			
ICK LED R 32 x 14 WLF ... D 32			R_{th} = 15,23 K/W
art. no.			
ICK LED R 32 x 14 G WLF ... D 32			
art. no.			
ICK LED R 33 x 10 WLF ... D 33			R_{th} = 17,6 K/W
art. no.			
ICK LED R 33 x 10 G WLF ... D 33			

Mounting material for semiconduct. → **E 37 – 41**
SMD-heatsinks → **B 38 – 40**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 8**
Thermally conductive material → **E 15**
Thermal conduct. foil WLFT 404/405 → **E 5**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

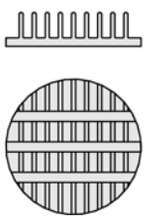
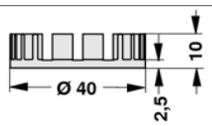
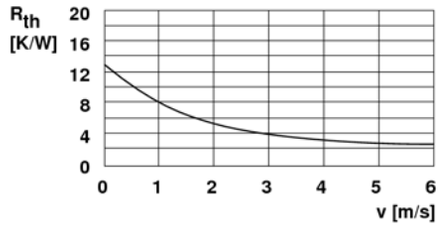
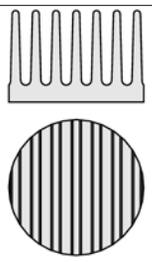
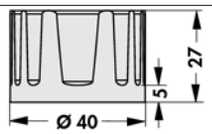
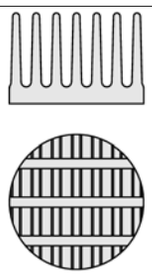
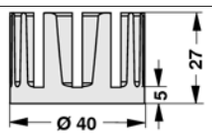
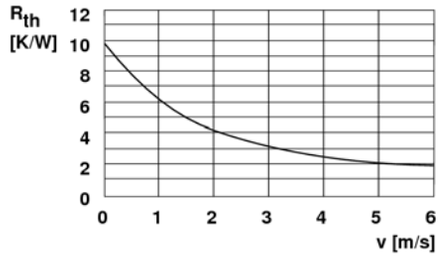
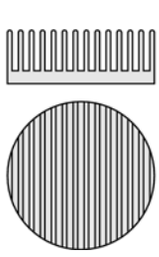
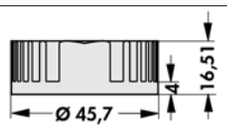
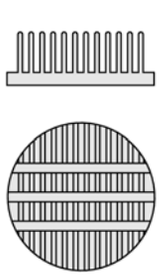
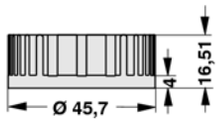
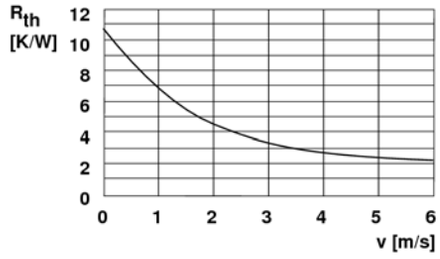
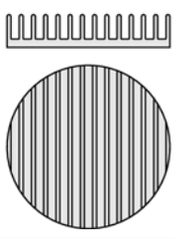
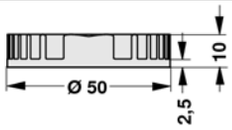
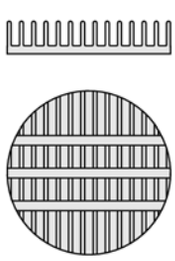
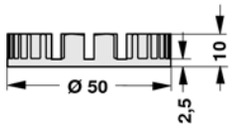
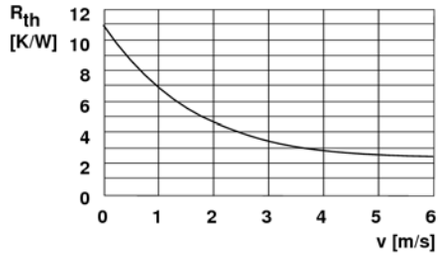
fischer elektronik

Heatsinks for LEDs

art. no.		
ICK LED R 33 x 16,5 WLF ... D 33		R_{th} = 13,87 K/W
art. no.		
ICK LED R 33 x 16,5 G WLF ... D 33		
art. no.		
ICK LED R 35 x 10 WLF ... D 35		R_{th} = 16,9 K/W
art. no.		
ICK LED R 35 x 10 G WLF ... D 35		
art. no.		
ICK LED R 36 x 12 WLF ... D 36		R_{th} = 12,88 K/W
art. no.		
ICK LED R 36 x 12 G WLF ... D 36		
art. no.		
ICK LED R 40 x 10 WLF ... D 40		R_{th} = 12,28 K/W

Mounting material for semiconduct. → E 37 – 41
SMD-heatsinks → B 38 – 40
Thermal conductive paste → E 13
Processor overview → B 2 - 8
Thermally conductive material → E 15
Thermal conduct. foil WLFT 404/405 → E 5
Hole pattern → A 21
Technical introduction → A 2 - 7

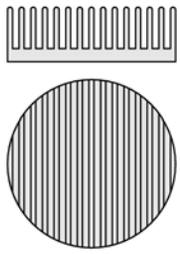
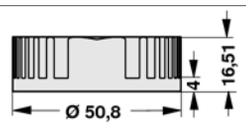
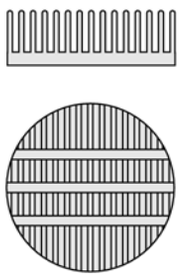
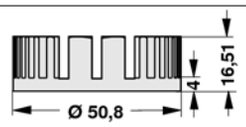
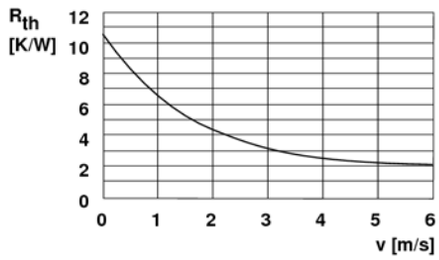
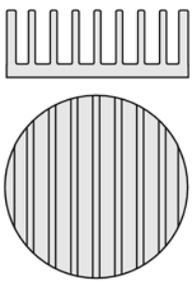
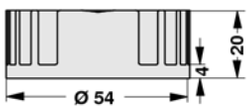
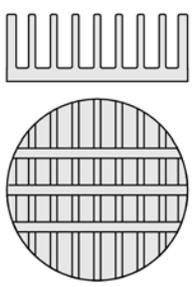
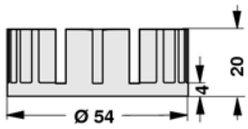
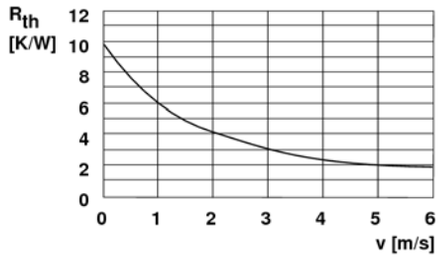
Heatsinks for LEDs

art. no.			
ICK LED R 40 x 10 G WLF ... D 40			
ICK LED R 40 x 27 WLF ... D 40			R_{th} = 9,41 K/W
ICK LED R 40 x 27 G WLF ... D 40			
ICK LED R 45,7 x 16,5 WLF ... D 45			R_{th} = 10,46 K/W
ICK LED R 45,7 x 16,5 G WLF ... D 45			
ICK LED R 50 x 10 WLF ... D 50			R_{th} = 10,57 K/W
ICK LED R 50 x 10 G WLF ... D 50			

Mounting material for semiconduct. → **E 37 – 41**
SMD-heatsinks → **B 38 – 40**
Thermal conductive paste → **E 13**
Processor overview → **B 2 - 8**
Thermally conductive material → **E 15**
Thermal conduct. foil WLFT 404/405 → **E 5**
Hole pattern → **A 21**
Technical introduction → **A 2 - 7**

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Heatsinks for LEDs

art. no.			
ICK LED R 50,8 x 16,5 WLF ... D 50			R_{th} = 10,17 K/W
art. no.			
ICK LED R 50,8 x 16,5 G WLF ... D 50			
art. no.			
ICK LED R 54 x 20 WLF ... D 54			R_{th} = 9,48 K/W
art. no.			
ICK LED R 54 x 20 G WLF ... D 54			

Mounting material for semiconduct. → E 37 – 41
SMD-heatsinks → B 38 – 40
Thermal conductive paste → E 13
Processor overview → B 2 - 8
Thermally conductive material → E 15
Thermal conduct. foil WLFT 404/405 → E 5
Hole pattern → A 21
Technical introduction → A 2 - 7

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